MYiR Make Your Idea Real

Product Brochure

A Global Provider of Embedded SOMs & Solutions

www.myirtech.com

2024.08

Company Profile

MYIR Electronics Limited (MYIR for short), established in 2011, is a global provider of embedded System-On-Modules (SOMs) and comprehensive solutions based on various architectures such as ARM, FPGA, RISC-V, and AI. We cater to customers' needs for large-scale production, offering customized design, industry-specific application solutions, and one-stop OEM services.

MYIR, recognized as a national high-tech enterprise, is also listed among the "Specialized and Special new" Enterprises in Shenzhen, China. Our core belief is that "Our success stems from our customers' success" and embraces the philosophy of "Make Your Idea Real, then My Idea Realizing!"

ISO 14001 ISO 9001

15+ years
Experience in the Embedded Industry

45+ %
R&D Personnel

5,000+ M²
R&D and Manufacturing Base

150+
Patents & Honors

30,000+
Worldwide Customers

Table of Contents

History

2011-2012

- Shenzhen Headquarter Established
- Beijing Office Established
- Shanghai Office Established
- Became ARM Approved Partner
- Became Xilinx Design Partner

2013-2017

- Became TI Design Network Partner
- Became NXP Approved Partner
- Became IDH Partner of AVNET
- Wuhan R&D Center Established
- Head Office Moved to Yunli Smart Park

2018-2021

- SMT Factory Established in Guanlan, Shenzhen
- Became ST Authorized Partner
- Became SemiDrive Design Partner
- Mouser Became Distributor
- Digi-key Became Distributor
- Qualified as National High-tech Enterprise
- ISO9001 certificated
- ISO14001 certificated

2022-2024

- Became IDH Partner of Renesas
- Became AllWinner Design Partner
- Awarded Quality Supplier of NARI Group
- Awarded Quality Supplier of XJ Group
- Honored with The Partner Award from ST
- Awarded with "Shenzhen Specialized and Special New Enterprise"

Main Business

- System-on-Modules (SOMs)
- Single Board Computers
- Solutions
- ODM Services
- OEM Services

Application Fields

- EV Charging Station
- Energy Storage
- Electric Power
- PLC
- Industrial Automation
- Industrial Gateway
- Commercial Display
- Medical Devices
- Engineering Machinery
- Rail Transport
- Industrial HMI
- AI Edge Computing

Corporate Culture

Mission

Laying the foundation for digital, intelligent, and networked embedded products to enable intelligent manufacturing and smart living.

Vision

To become the most trusted provider of embedded SOMs for industrial customers worldwide.

Values

Co-creation, win-win collaboration, and sharing, aiming to create maximum value for customers.

Information Management Platform

MYIR has developed a comprehensive range of professional and sophisticated enterprise-level information management platforms. These platforms enable comprehensive digital management across various dimensions, including material supply chain, product research and development, customer management, project management, employee management, production management, and more. Through these platforms, MYIR aims to achieve business digitization, management visualization, and intelligent production.

Enterprise Management

ERP System

Customer Management

CRM System

Supplier Management

SRM System

Product Management

PLM System, DFX System

Production Management

MES System, iDAS Electrostatic Monitoring System, WMS Intelligent Storage System

Business Philosophy

Leading Technology

Continuously engaging in technological innovation to provide customers with cutting-edge technologies and products.

Professional Service

Systematically establishing a customer service framework and offering comprehensive technical support throughout the entire sales cycle, from pre-sales to post-sales.

Delivery Commitment

Guaranteeing a product lifecycle of no less than 10 years.

Quality Assurance

The ISO management system runs through the entire process, from material selection to R&D, product testing, production, and shipment.

Qualifications and Honors

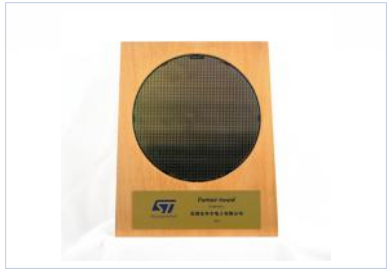
National High-Tech Enterprise

Shenzhen Specialized and Special New Enterprise

ISO9001

ISO14001

IDH Partner of Renesas



Partner Award from ST for MYIR

Quality Supplier of XJ Power Co., Ltd.

Quality Supplier of NARI Group

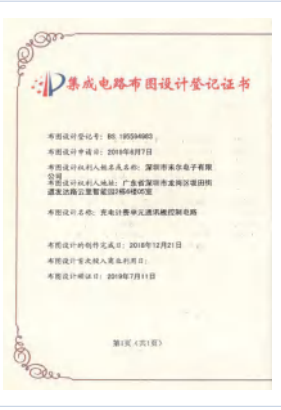
CE Certification

RoHS Certification

Software Copyright

Certificate of Utility Model Patent

Certificate of Invention Patent



Certificates of the Registration for Integrated Circuit Layout Designs

Strategic Partners

Our Clients (Part)

R&D Capabilities

MYIR has established R&D centers in both Shenzhen and Wuhan, and boasts a senior technical R&D team. Approximately 45% of our personnel are dedicated to R&D, and all of them possess a bachelor's degree or higher. The core and backbone members of our R&D team possess extensive experience in the embedded industry, having accumulated more than 10 years of professional expertise in the field. They are equipped with cutting-edge design concepts and practices specially tailored for high-volume product applications. Our products exhibit industry-leading innovation, reliability, and stability, and we have filed for numerous patents, copyrights, and various certifications, exceeding a total of 100.

Excellent, Scientific, and Systematic R&D Management

Complete R&D Management

Adopting the IPD process management concept, combined with modern information system management tools

- Project Management
- Task Management
- Defect Management
- Review Management
- Design Documentation
- Code Management
- Knowledge and Experience Management

Design Capability Optimization

Establish complete and unified key design node control

- Test Example
- Schematic/ PCB CheckList
- Standard Circuit Library
- DFX Management
- High-speed Signal Design and Simulation
- Material AVL Preferred Library

Technology and Skills

Hardware Development

- Standard Component Library
- Standard Circuit Diagram
- Complete Schematic (PCB CheckList)
- FMEA Analysis
- SI Simulation Design

Software Development

- Multiple OS Development Capabilities
  Linux | android | RTOS
- Kernel Porting and Driver Development Capabilities
- System Optimization Capabilities
  (boot time, real-time performance, multi-system backup, OTA, security, etc.)
- System Customization Capabilities Conform to Industrial and Power scenarios
- Protocol Development and Application Development Capabilities

Testing Capability

The MYIR R&D and testing team adheres to a scientific, rigorous, objective and fair attitude, relying on a comprehensive testing system and professional, extensive testing experience. All products are strictly tested in accordance with relevant national standards, industry standards, and company standards, ensuring that all the product has long-term stability, reliability, mass production capability, and data traceability.

Signal Test

Standards Range

- Corresponding chip data manual

Main Evaluation Items

Power Test

- ✓ Ground Impedance Test
- ✓ Ripple Test
- ✓ Up-down Waveform Test
- ✓ Power On/Off Timing Test
- ✓ Power Consumption Test
- ✓ Power Noise Test

Signal Test

- ✓ I2C Test
- ✓ I2S Test
- ✓ SDIO Test
- ✓ Clock Test
- ✓ Ethernet Test
- ✓ UART Test
- ✓ CAN Test
- ✓ RS232/RS485 Test

EMC Test

Standards Range

- EN55032
- NB/T33008.1
- IEC61000-4
- GB/T 17626

Main Evaluation Items

EMI: Electromagnetic Interference

- ✓ RE: Radiation Emission
- ✓ CE: Conducted Emissions
- ✓ Harmonics: Harmonic Current
- ✓ Flicker: Flashing

EMS: Electromagnetic Sensitivity

- ✓ RS: Radiation Immunity
- ✓ CS: Conducted Immunity
- ✓ ESD: Electrostatic Immunity
- ✓ Surge: Surge Immunity
- ✓ EFT/B: Electric Fast Transient Pulse Group
- ✓ PMS: Power Frequency Magnetic Field Anti-interference Degree
- ✓ Dips: Voltage Drop/ Short Interruption

Certification

Standards Range

- EN 55032: 2015
- EN 61000-3-3: 2013
- EN 55035: 2017
- EN IEC 61000-3-2: 2019
- IEC62321

Main Evaluation Items

- ✓ CE Certification
- ✓ RoHS Certification

Reliability Test

Standards Range

- GB/T 2423.2-2008
- GB/T 2423.8-1995
- GB/T 2423.17-2008
- GB/T 2423.22-2012
- GB/T 2423.10-2019
- GB/T 19056-2012
- GB/T 2423.5-2019

Main Evaluation Items


High Temperature Test


Aging Test


Vibration Testing


Shock Test


Salt Spray Test


MTBF Test

Technical Services

MYIR is customer-oriented, and provides comprehensive technical support and services for various issues encountered by customers during the processes of project selection, project approval, project development, product testing, small-batch trial production, and mass production. The company's frontline engineering team assists customers in solving technical problems through various channels such as online communication, telephone, email, remote video conferencing, and on-site services, and provides abundant learning materials. MYIR is committed to accelerating the customer's development process, reducing the customer's development costs, ensuring the quality of the customer's products, and enhancing the competitiveness of the customer's products in the market.

Pre-sales Service

1. **Communication and Requirement Analysis**
   The technical service team actively and comprehensively participates in analyzing and understanding customer requirements.
2. **Consultative Product Selection Guidance**
   Our professional team recommends the most suitable SOM optimized for performance, functionality, and cost-effectiveness.
3. **Software and Hardware Framework Construction**
   We ensure that the overall software and hardware system design aligns with and fulfills the customer's specific requirements.
4. **Prototype Verification**
   We ensure the feasibility and stability of the system design for the selected platform.
5. **Project Technical Risk Assessment**
   We identify potential risks, propose effective solutions, and formulate countermeasures.

In-sales Service

1. **Developer Resources Download**
   Provide detailed documentation and software packages for products.
2. **Schematic and PCB Design Guidance**
   Ensure that the circuit design layout is reasonable and meets system performance and stability requirements.
3. **Schematic and PCB Review**
   Avoid potential circuit board design issues and defects.
4. **Assist with Driver Development**
   Ensure compatibility between hardware and software, and verify the functionality and performance of underlying drivers.
5. **Assist with Middleware Porting**
   Ensure the normal operation and functional integrity of the system.
6. **Assist with System Optimization and Cropping**
   Improve system performance and stability while reducing resource consumption.
7. **Material Selection Guidance**
   Provide suggestions on quality, performance, and pricing to enhance product competitiveness.
8. **Test Plan Guidance**
   Ensure the project meets quality standards before launch and guarantee product stability.
9. **Production Process Guidance**
   Provide production process guidance documents as a reference to ensure product efficiency and quality.
10. **R&D Sampling Service**
    Provide one-stop sampling services and reports, analyze potential issues, and provide improvement suggestions.

After-sales Service

- **Technical Support**
  Respond to customer queries in a timely manner, primarily providing support through emails, phone calls, or online meetings.
- **Problem Recording and Organization**
  Maintain separate records for each customer issue to track the root cause and implement continuous improvement measures.
- **Warranty**
  Offer product repair and exchange services. MYIR's production system ensures batch traceability at both the product and material levels, facilitating problem identification, analysis, resolution, as well as the provision of analysis reports and usage suggestions.
- **Knowledge Sharing**
  Aid customers in enhancing their understanding of product usage through articles, documentation and videos.
- **Output 8D report**
  The report encompasses a comprehensive analysis, including problem description, root cause analysis, corrective actions, preventive measures, and improvement suggestions.

Quality Assurance

MYIR has implemented a series of inspection steps, including incoming inspection of materials, pre-assembly baking, solder paste printing inspection, online AOI, first article inspection, spot X-RAY inspection, IPQC patrol inspection, and QA outgoing inspection. We also conduct comprehensive real-time electrostatic protection monitoring. By adhering to the ISO9001 quality management system, we ensure a high product qualification rate for all outgoing products.

1 Project Management

Project initiation, PCB design, layout review, trial production summary, and transition to mass production review and summarize meetings to ensure the smooth transition of the project.

2 Incoming Materials Inspection

Material recognition, sample sealing, incoming inspection (appearance, function) to ensure raw material quality

3 Process Control

Track and inspect the factory production line, conduct sampling of finished products, timely feedback on production abnormalities, and track process improvement confirmations to ensure process quality

4 QA Outgoing Inspection

Conduct QA inspection, finished product sampling, packaging inspection to ensure finished product quality

5 Customer Feedback

Hold timely and effective customer complaint meetings, conduct root cause investigations and improvements, confirm effectiveness. Follow up with customers, adhering to customer-first principles

Systematic Warehouse Management

The warehouse uses X-ray automatic component counting machines and AI-enabled intelligent sensing shelves. For the electronic components warehouse, it maintains a controlled temperature and humidity, incorporates anti-static measures, and strictly adheres to a first-in-first-out inventory management protocol. It supports the issuance of materials for multiple work orders, enables real-time inventory tracking, prevents material loss and errors, seamlessly integrates with MES and ERP systems, and ensures traceability throughout the entire process of usage and management.

WMS Intelligent Warehousing System

Intelligent shelves, combined with a smart warehouse system, achieve zero material error.

Constant Temperature and Constant Humidity, Ensuring Safety

Integrated circuits and electronic components are stored in warehouses and cabinets maintained at constant temperature and humidity to ensure the effectiveness and reliability of materials.

A Complete Supply Chain System

We have a senior supply chain management team with over 10 years of industry experience. We offer comprehensive BOM material supply, component selection, and substitute recommendation services. With professional BOM engineers and strict, standardized IQC incoming material inspection standards, as well as original genuine product guarantees sourced from original manufacturers and primary agents, we ensure that we provide our customers with short delivery times, high-quality, and low-price component guarantees.

1,000+ Original Manufacturers and Agent Cooperation Partners (including some of them)

Production Capacity

MYIR has a 3,000-square-meter smart SMT factory, equipped with a Class 100,000 cleanroom and multiple SMT production lines. Leveraging advanced production equipment, sophisticated management systems, stringent quality control processes, a comprehensive supply chain network, and robust engineering support, we guarantee product quality throughout the entire process, from raw material sourcing to production and ultimately shipping. Our factory possesses a surface mount capability of over 5 million points per day, and all production processes adhere strictly to RoHS and REACH standards.

Complete Automated Production Equipment

Equipped with Panasonic imported high-speed dual-track SMT line, our factory has fully automatic solder paste printer, nitrogen reflow oven, wave soldering machine, AOI, SPI and X-RAY inspection machines, intelligent first article inspection instrument, intelligent solder paste management cabinet, automatic PCB router machine, conformal coating machine, laser engraving machine, BGA rework stations, and other equipment. It is also supported by MES intelligent management system, intelligent warehousing system, ERP system, and static electricity management system.

Automatic Solder Paste Printer

Automatic Solder Paste Inspection Machine (3D SPI)

NPM-D3A SMT Machine

NPM-TT2 SMT Machine

Online AOI

Automatic Coating Production Line

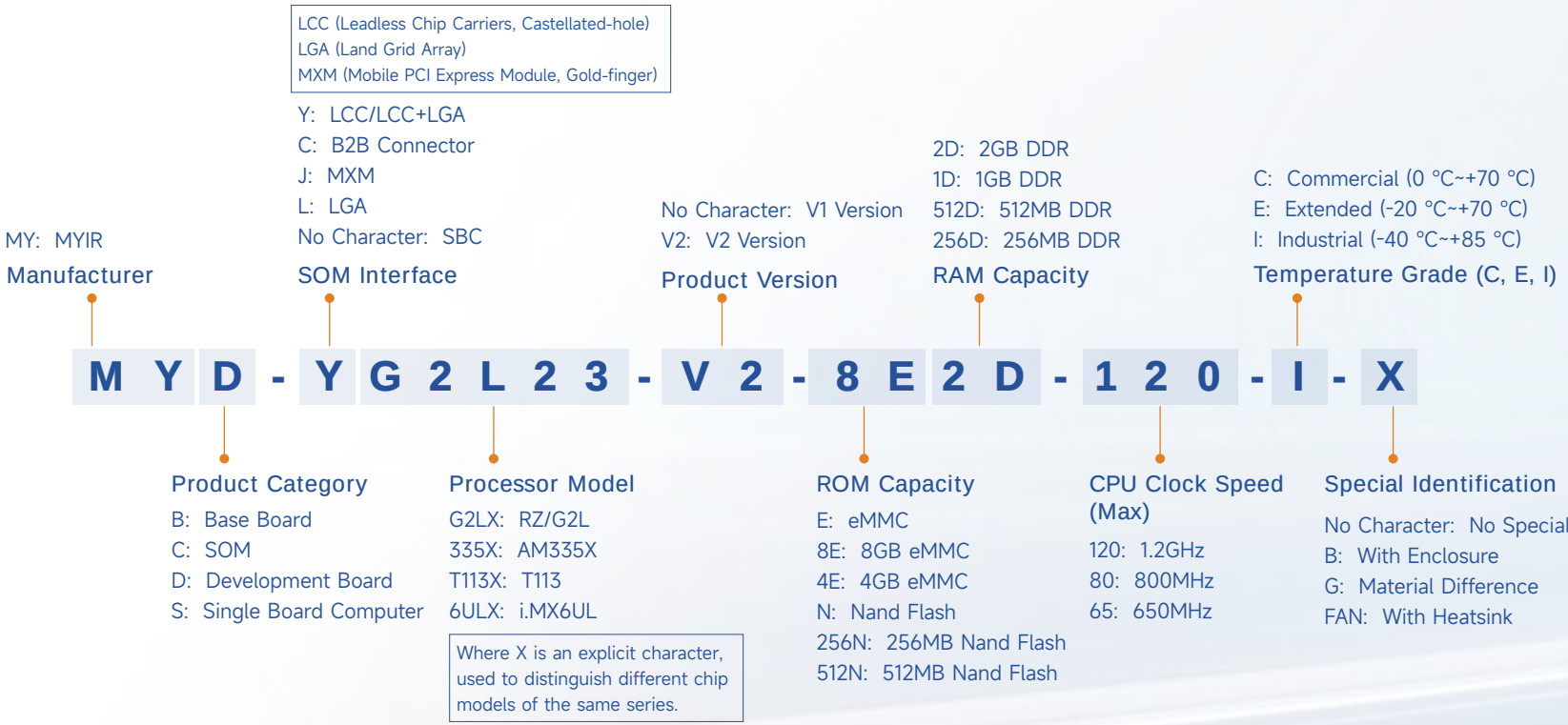
Excellent Production Environment Conditions

The production workshop equipment and assembly line stations are equipped with LoRa electrostatic monitoring nodes. If the electrostatic levels exceed the standard, audible and visual alarms will be triggered. The real-time data collected by the gateway will be transmitted to the data backend. Overall electrostatic data from the workshop can be dynamically displayed on a large screen in multiple dimensions.

Integrated Manufacturing Information Management System

An industry-leading integrated manufacturing information management system (MES) that enables seamless integration with ERP, WMS, SRM and other systems, improving the real-time nature and transparency of factory management, as well as the level of full-process traceability and error prevention control for products.

Naming Convention



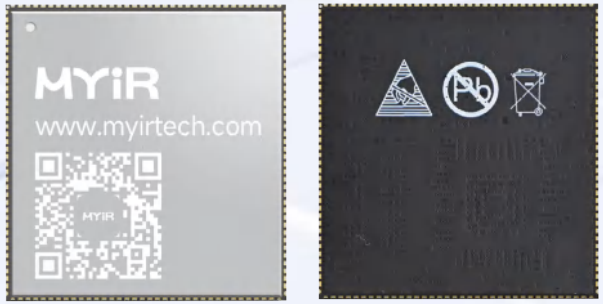
SOM Selection Table

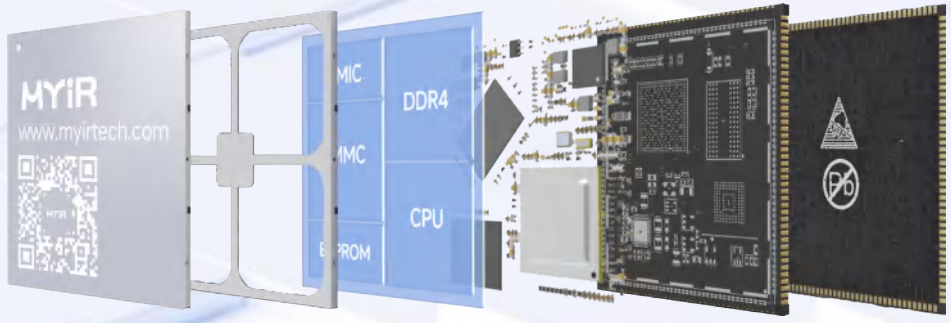
Performance \ CPU Vendor	STM32	NXP	AMD XILINX	Texas Instruments
Entry-level A7/A8/A9/ A55/FPGA 1-2 Cores	**MYC-YF13X** P19 ST STM32MP135 A7@1.0GHz 2×1000M ETH, 8×UART, Parallel CSI 2×CAN FD, Parallel LCD	**MYC-Y6ULX-V2** P27 NXP i.MX6UL/i.MX6ULL A7@528MHz 2×100M ETH, 2×CAN, 8×UART Parallel LCD, Parallel CSI	**MYC-C/Y7Z010/20-V2** P36 AMD-Xilinx XC7Z010/20 ARM: 2×A9@667MHz/766MHz, FPGA: 28K/ 85K 1000M ETH, LCD, USB2.0, CAN UART	**MYC-C335X-V4** P29 TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD	**MYC-C335X-GW** P32 TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD
	MYC-YA15XC-T P20 ST STM32MP151 A7@650MHz+M4@209MHz 1000M ETH, 8×UART Parallel LCD, Parallel CSI		**MYC-C7Z015** P38 AMD-Xilinx XC7Z015 ARM: 2×A9@766MHz FPGA: 74K 1000M ETH, LCD, USB2.0, CAN UART, PCIE2.0, SFP	**MYC-Y335X-V2** P30 TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD	**MYC-J335X-V2** P31 TI AM335X A8@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD
	MYC-YA157C-V3 P21 ST STM32MP157 2×A7@650MHz+M4@209MHz 1000M ETH, 8×UART, MIPI DSI 2×CAN FD, 3D GPU		**MYC-J7A100T** P40 AMD-Xilinx Atrix 7A100T FPGA: 101K 2×1000M ETH, HDMI, UART Camera, 2×SFP, PCIE2.0		**MYC-C437X-V2** P33 TI AM437X A9@1.0GHz 2×1000M ETH, 2×CAN, 6×UART 3D GPU, PRU, Parallel LCD
Mid-range A35/A53/A55 2-4 Cores		**MYC-C8MMX-V2** P26 NXP i.MX 8M Mini 4×A53@1.8GHz+M4@400MHz 1×1000M ETH, 4×UART, 1×PCIE2.0 MIPI DSI, MIPI CSI, 3D GPU, VPU			**MYC-YM62X** P28 TI AM62X 1/2/4×A53@1.4GHz+M4F@400MHz 2×1000M ETH, 3×CAN FD, 9×UART 3D GPU, PRU, GPMC, LVDS
		MYC-LMX9X P22 NXP i.MX93 2×A55@1.7GHz+M33@250MHz 2×1000M ETH, 2×CAN FD, 8×UART LVDS, MIPI DSI, MIPI CSI			
High-end A53/A55/A72 2-8 Cores		**MYC-JX8MPQ** P25 NXP i.MX 8M Plus 4×A53@1.8GHz+M7@800MHz 2×1000M ETH, 2×CAN FD, PCIE2.0, 2×USB3.0, NPU, MIPI DSI, HDMI	**MYC-CZU3EG/4EV/5EV-V2** P39 Xilinx XCZU3EG/4EV/5EV ARM: 4xA53@1200MHz+2xR5@600MHz FPGA: 154K(3EG)/192K(4EV)/256K(5EV) 1000M ETH, CAN, LCD, USB3.0 FMC, DP, SATA3.0, UART, PCIE2.0		
		MYC-J1028X P23 NXP LS1028A 2×A72@1.5GHz 2×1000M ETH, DP1.3/eDP1.4, SATA 3.0 2×USB3.0, 2×PCIE3.0, 4×TSN Switch			
		MYC-JX8MMA7 P24 NXP i.MX 8M Mini+AMD Atrix 7 ARM: 4×A53@1.8GHz+M4@400MHz, FPGA: 23K 1000M ETH, 2×USB2.0, 4×UART, 3×SPI, MIPI DSI, MIPI CSI			

SOM Selection Table

Performance \ CPU Vendor	RENESAS	ALLWINNER	芯驰 SemiDrive	nuvoTon	Rockchip
Entry-level A7/A8/A9/ A55/FPGA 1-2 Cores	**MYC-YG2UL** P34 Renesas RZ/G2UL A55@1.0GHz+M33@200MHz 2×1000M ETH, 2×USB2.0, 1×MIPI CSI 7×UART, 2×CAN FD, 3×SPI, 1×RGB	**MYC-YT113i** P43 Allwinner T113-i 2×A7@1.2GHz 1000M ETH, 6×UART, Parallel CSI MIPI DSI, RGB, 2×LVDS, 2×CAN **MYC-YT113X** P44 Allwinner T113-S3 2×A7@1.2GHz 1000M ETH, 6×UART, Parallel CSI MIPI DSI, RGB, 2×LVDS, 2×CAN			
Mid-range A35/A53/A55 2-4 Cores	**MYC-YG2LX** P35 Renesas RZ/G2L 2×A55@1.2GHz+M33@200MHz 2×1000M ETH, 2×USB2.0, 7×UART, 2×CAN FD, 3D GPU, VPU, MIPI DSI	**MYC-YT507H** P41 Allwinner T507H 4×A53@1.5GHz 1000M ETH, 1×FE, 6×UART 4×USB2.0, 2×LVDS, RGB, 3D GPU		**MYC-LMA35** P47 Nuvoton MA35D1 2xA35@800MHz+M4@180MHz 2×1000M ETH, 4×CAN FD, 17×UART 16bit EBI, 24bit RGB, 2×USB2.0	**MYC-LR3568** P46 Rockchip RK3568 4 x A55@Up to 2.0GHz 2×1000M ETH, 2×HDMI, 2×MIPI CSI eDP1.3, 4×USB, 2×PCIe3.0, SATA3.0
High-end A53/A55/A72 2-8 Cores		**MYC-LT527** P42 Allwinner T527 8×A55@1.8GHz+RISC-V@200MHz 2×1000M ETH, HDMI, MIPI DSI/CSI 3×USB, 2×CAN, 10×UART, 4×SPI	**MYC-JD9360** P45 SemiDrive D9360 6×A55@1.6GHz+R5@800MHz 2×1000M ETH, 2×USB3.0, 2×PCIe3.0 4×CAN FD, 8×SPI, 12×I2C, 8×PWM		

Advantages of MYIR's System-On-Modules





Innovative Design

LCC/LGA Packaging

Ensures more stable and reliable signal connection, superior vibration resistance, and convenience for mass production

Shield Design

Resistant to signal interference and dust, while supporting customized LOGO to enhance customer brand value

Compact Design

Features a small size and flexible design, making it suitable for various sizes of products, especially those with limited structural space

Excellent Quality

Rigorous Testing

The SOMs undergo six rigorous tests, including signal tests, high and low temperature tests, aging tests, electrostatic tests, over 5,000 power-on and power-off tests, and MTBF tests, to ensure product stability.

Compliance with International Certification Standards

Adopting international SGS as a certification testing partner, we provide CE and RoHS certification reports

Smart Factory

MYIR's own factory, equipped with advanced production equipment and adopting MES systems, ensures high-quality and traceability of products

Competitive cost

Scale Effect

With over one million SOMs sold annually, we achieve excellent bulk material costs through mass production

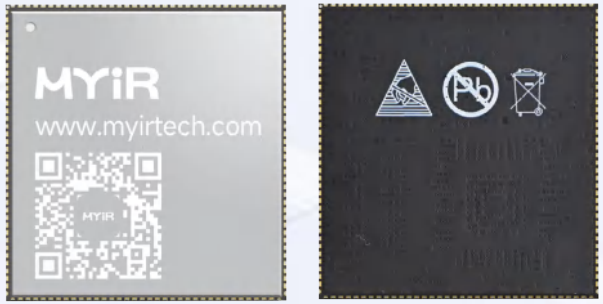
Packaging Advantage

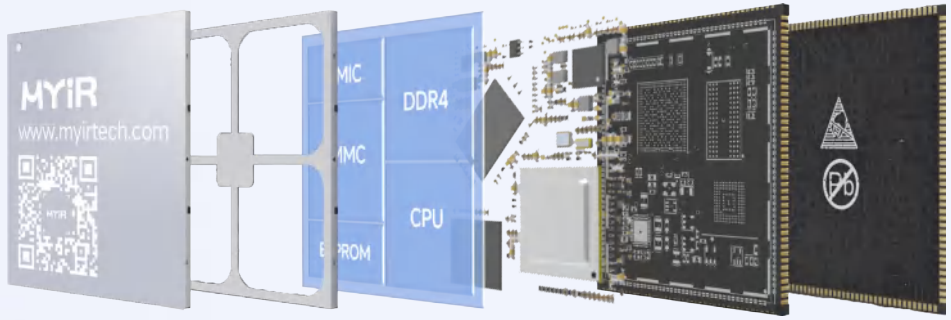
The SOMs adopt an LCC/LGA packaging design, which saves the cost of board-to-board connectors

Supply Chain Management

Establishing close cooperation relationships with original manufacturers enables us to obtain more competitive chip price support

Advantages of MYIR's System-On-Modules





Quick Delivery and Long Lifecycle

Short lead time

By implementing a comprehensive inventory management system for our standard products, we guarantee a shortened lead time for both sample and bulk orders.

Long lifecycle

We guarantee a supply duration exceeding 10 years. In case of material discontinuation, we have established a comprehensive product change process and notification policy to mitigate any potential disruptions.

Long-term maintenance

Our commitment extends to providing ongoing software maintenance and regular updates for the BSP package, ensuring its continued reliability and performance over time.

Full-service technical support

Pre-sales service

We offer optimal platform recommendations, feasibility assessments, software and hardware framework setups, and prototype function verifications during the selection phase, guiding you through the initial stages of your project seamlessly.

In-sales service

During the design phase, we provide schematic diagram and PCB guidance and review, driver debugging, middleware transplantation, and system optimization, ensuring the smooth progress of your development efforts.

After-sales service

We maintain prompt email communication with our FAE team, offering remote assistance to resolve any issues that may arise. We document the entire process and provide an 8D report, ensuring transparency and continuous improvement.

Abundant development resources

Hardware documentation

Comprehensive product manuals, hardware design guides, hardware user manuals, and pin usage tables for our SOMs, facilitating easy integration and customization.

Software documentation

Detailed quick start guides, software development guides, software evaluation guides, and application notes, enabling efficient software development and deployment.

Design materials

Access to our baseboard schematic and PCB source files, BSP software source code, and industry application demos, providing a solid foundation for your design and development efforts.

MYC-YF13X

- ST STM32MP135 Processor, Cortex-A7@1.0GHz
- DDR3L, Nand Flash/eMMC, EEPROM
- LCD-TFT Parallel Display Interface, 16-bit Camera, 2x USB2.0, 2x CAN-FD, 2x Gigabit Ethernet
- 37mm x 39mm; LCC Package, 148-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

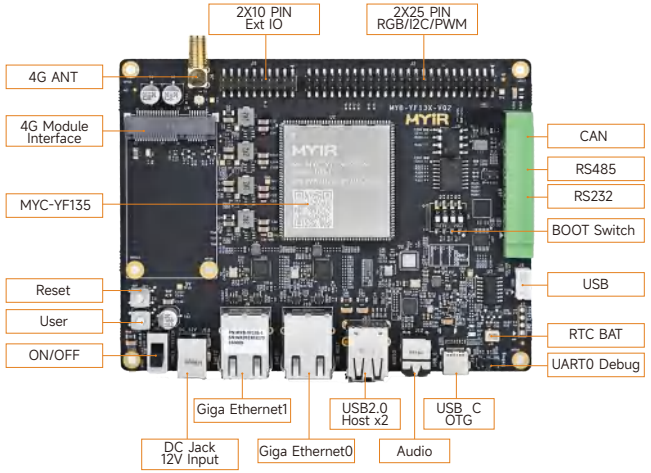
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YF135-256N256D-100-I	STM32MP135DAF7	Cortex-A7@1.0GHz	256MB DDR3	256MB Nand Flash	32Kbit EEPROM	LCC 148PIN	-40°C~+85°C	37mm x 39mm	Linux	MYD-YF135-256N256D-100-I
MYC-YF135-4E512D-100-I			512MB DDR3	4GB eMMC						MYD-YF135-4E512D-100-I

Peripherals/Interfaces

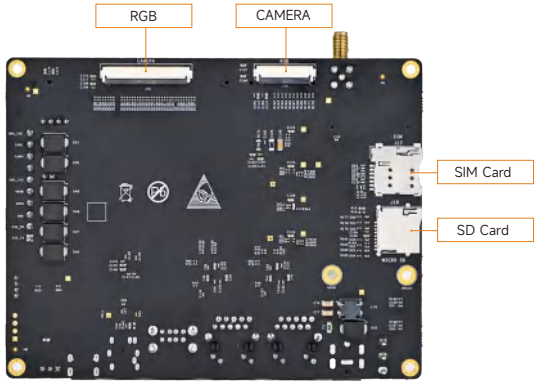
Communications	2×RGMII, 2×CAN FD, 2×USB2.0, 8×UART, 5×SPI, 5×I2C
Multimedia	RGB, DCMI, 2×SAI, 3×I2S
Others	12-bit 19-ch ADC, 12-bit 18-ch ADC, SWD

Key Applications

Industrial HMI | Industrial Gateway | Industrial Control | Power Management



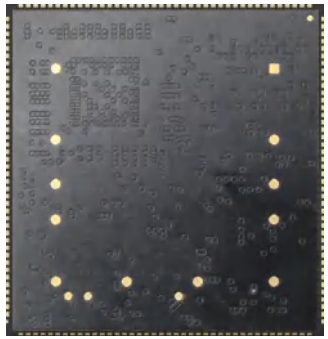
MYD-YF13X Development Board Top-view



MYD-YF13X Development Board Bottom-view

MYC-YA15XC-T

- ST STM32MP151 Processor, Cortex-A7@650MHz + Cortex-M4@209MHz
- DDR3L, Nand Flash/eMMC, EEPROM
- Gigabit Ethernet, 2x USB 2.0, 8x UART, 6x SPI, 6x I2C
- 37mm x 39mm; LCC Package, 148-pin; 0 to 70 °C Commercial, -40°C~+85°C Industrial; Linux OS



Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YA151C-256N256D-65-C-T	STM32MP151AAC3	Cortex-A7@650MHz +Cortex-M4@209MHz	256MB DDR3	256MB Nand Flash	32Kbit EEPROM	LCC 148PIN	0°C~+70°C	37mm × 39mm	Linux	MYD-YA151C-V2-256N256D-65-C-T
MYC-YA151C-256N256D-65-I-T							-40°C~+85°C			MYD-YA151C-V2-256N256D-65-I-T
MYC-YA151C-4E512D-65-C-T			512MB DDR3	4GB eMMC			0°C~+70°C			MYD-YA151C-4E512D-65-C-T
MYC-YA151C-4E512D-65-I-T							-40°C~+85°C			MYD-YA151C-4E512D-65-I-T

Peripherals/Interfaces

Communications	RGMII, 2×USB2.0, 8×UART, 6×SPI, 6×I2C
Multimedia	RGB, DCMI, 4×SAI, 3×I2S
Others	2×16-bit 20-ch ADC, SWD

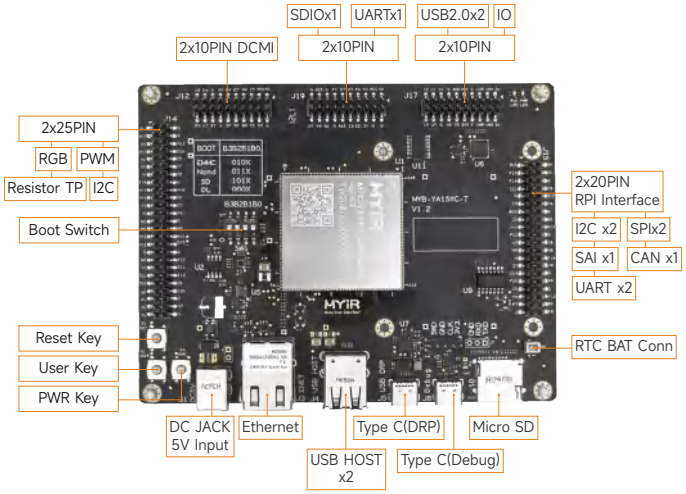
Key Applications

HMI

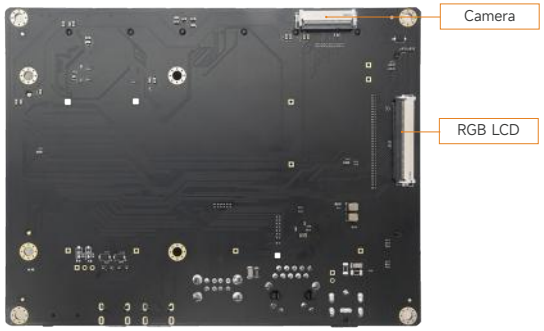
Medical Device

Industrial Manufacturing

Petroleum & Chemical

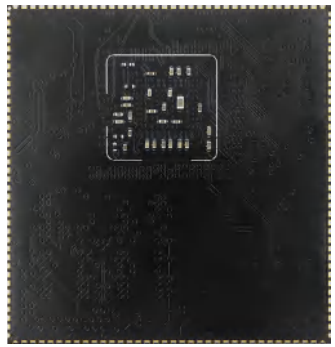


MYD-YA15XC-T Development Board Top-view



MYD-YA15XC-T Development Board Bottom-view

MYC-YA157C-V3



- ST STM32MP157 Processor, 2x Cortex-A7@650MHz + Cortex-M4@209MHz
- DDR3, eMMC, Ethernet PHY
- Gigabit Ethernet, 2x CAN, 2x USB2.0, 8x UART, 6x SPI, 6x I2C
- 43mm x 45mm; LCC Package, 164-pin; 0 to 70 °C Commercial, -40°C~+85°C Industrial; Linux / Ubuntu OS

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YA157C-V3-4E512D-65-C	STM32MP157AAC3	2×Cortex-A7@650MHz +Cortex-M4@209MHz	512MB DDR3L	4GB eMMC	Ethernet PHY	LCC 164PIN	0°C~+70°C	43mm x 45mm	Linux Ubuntu	MYD-YA157C-V3-4E512D-65-C
MYC-YA157C-V3-4E512D-65-I							-40°C~+85°C			MYD-YA157C-V3-4E512D-65-I

Peripherals/Interfaces

Communications	RGMII, 2×CAN FD, 2×USB2.0, 8×UART, 6×SPI, 6×I2C
Multimedia	RGB, MIPI DSI, 4×SAI, 3×I2S
Others	2×16-bit 20-ch ADC, SWD

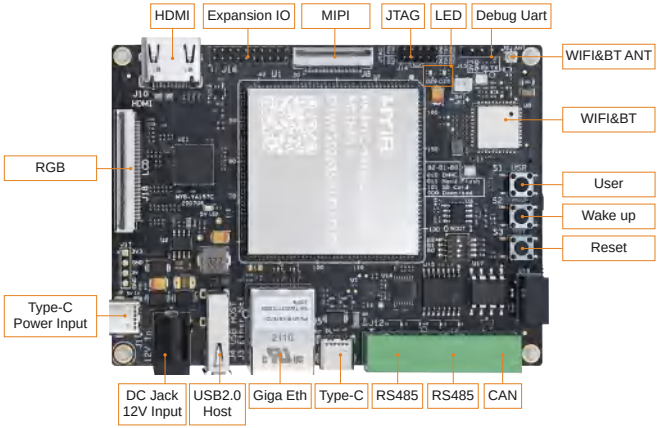
Key Applications

HMI

Medical Device

Industrial Manufacturing

Petroleum & Chemical

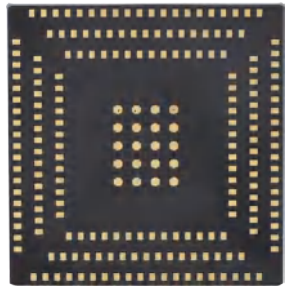


MYD-YA157C-V3 Development Board Top-view

MYD-YA157C-V3 Development Board Bottom-view

NXP | MYC-LMX9X

- NXP i.MX 93 Processor, 2*Cortex-A55@1.7GHz + Cortex-M33@250MHz
- 0.5 TOPS NPU for Cost-effective and Energy-efficient ML Applications
- 2x Gigabit Ethernet (one TSN-based), 2x CAN FD, 8x UART, 8x I2C, 8x SPI
- LPDDR4, eMMC, EEPROM, 37mm x 39mm; LGA Package, 218-pin; -40°C~+85°C Industrial
- Linux OS (Yocto based with QT / Debian)



Part Selections (Other Configurations can be Customized for Mass Production)

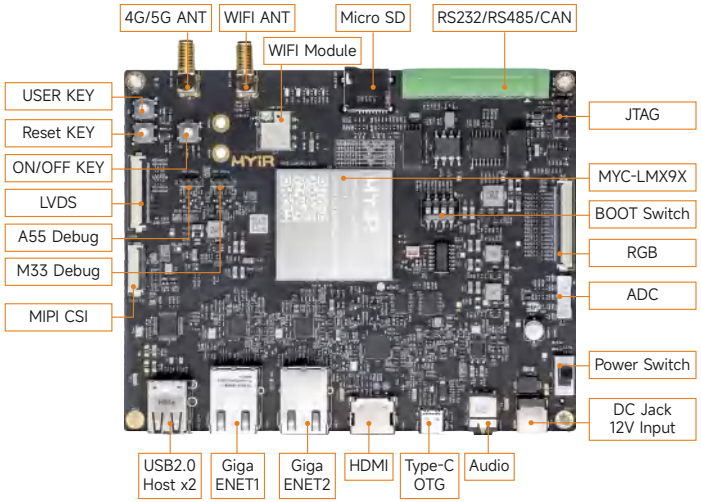
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LMX9352-8E1D-170-I	MIMX9352CVVXMAB	2×Cortex-A55@1.7GHz+ Cortex-M33@250MHz	1GB LPDDR4	8GB eMMC	32KB EEPROM	LGA 218PIN	-40°C~+85°C	37mm x 39mm	Linux Debian	MYD-LMX9352-8E1D-170-I
MYC-LMX9352-8E2D-170-I			2GB LPDDR4							MYD-LMX9352-8E2D-170-I

Peripherals/Interfaces

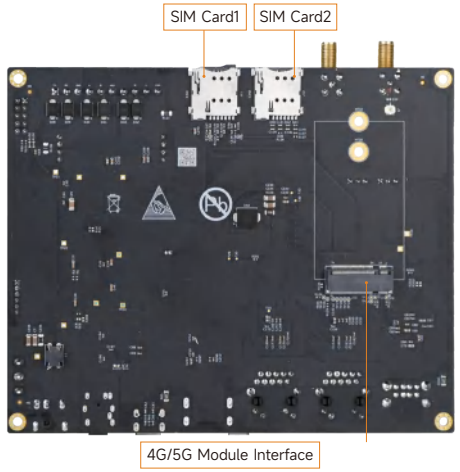
Communications	2×RGMII, 2×CAN FD, 2×USB2.0, 8×UART, 8×SPI, 8×I2C, 2×I3C
Multimedia	MIPI DSI, LVDS, RGB, MIPI CSI, Parallel CSI , 3×SAI
Others	12bit 4ch ADC, JTAG

Key Applications

Charging Pile | Motion Controller | Engineering Machinery | Medical Device



MYD-LMX9X Development Board Top-view



MYD-LMX9X Development Board Bottom-view

NXP | MYC-J1028X

- NXP LS1028A Processor, 2*Cortex-A72@1.5GHz, DDR4, eMMC, EEPROM
- 6x Gigabit Ethernet (TSN-based), 2x USB3.0, 2x CAN FD, 6x UART, 3x SPI, 1x SATA3.0
- Support DP Display (DP1.3 and eDP 1.4, resolution up to 4K@60FPS)
- 45mm x 82mm; MXM 3.0 Gold-finger Interface, 314-pin; -40°C~+85°C Industrial;
- Supports Ubuntu and Real-time Edge Images based on Linux

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-J1028N-8E2D-150-I	LS1028AXN7PQA	2×Cortex-A72@1.5GHz	2GB DDR4	8GB eMMC	32Kbit EEPROM	MXM 314PIN	-40°C~+85°C	45mm x 82mm	Linux Ubuntu	MYD-J1028N-8E2D-150-I

Peripherals/Interfaces

Communications	SGMII, QSGMII, RGMII, 2×PCIE3.0, SATA 3.0, 2×USB3.0, 2×CAN FD, 6×UART, 3×SPI, 8×I2C
Multimedia	eDP, 6×SAI
Others	JTAG

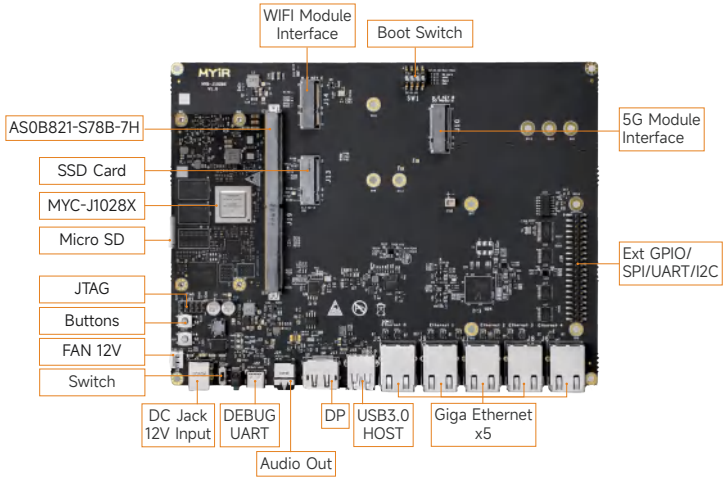
Key Applications

Automotive Electronics

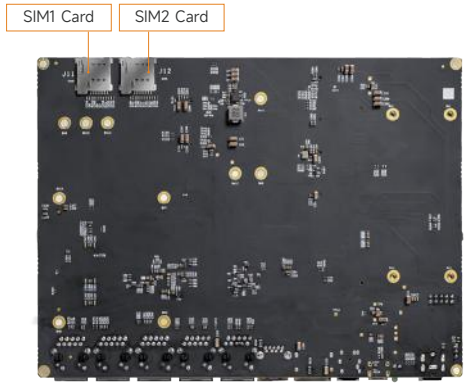
Industrial Routers

Industrial Control

Edge Computing

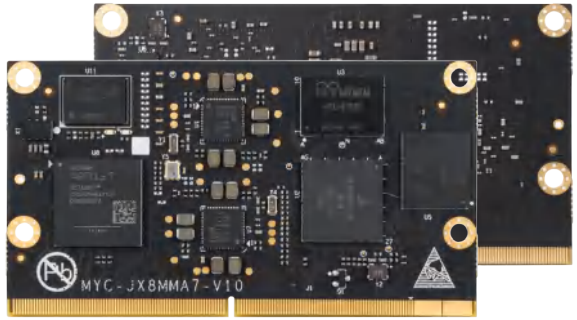


MYD-J1028X Development Board Top-view



MYD-J1028X Development Board Bottom-view

NXP & AMD | MYC-JX8MMA7



- i.MX 8M Mini + XC7A25T Aritx-7, 4*Cortex-A53@1.8GHz + Cortex-M4@400MHz + FPGA
- ARM: LPDDR4, eMMC, QSPI Flash; FPGA: DDR3, QSPI Flash
- Integrated 2D/3D GPU and 1080p VPU, Two PMIC (one for ARM and one for FPGA)
- 45mm x 82mm; MXM 3.0 Gold-finger Interface, 314-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

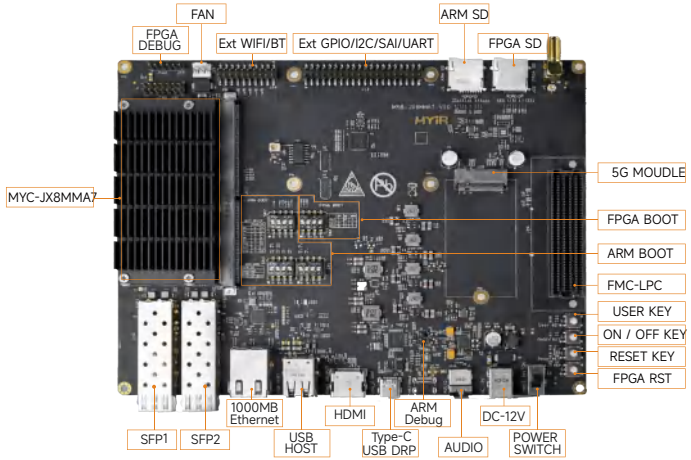
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-JX8MMA7-8E2D-32Q256D-160-I	ARM: MIMX8MM6CVTKZAA FPGA: XC7A25T-2CSG325I	4×Cortex-A53@1.6GHz+ Cortex-M4@400MHz FPGA: 23K	ARM: 2GB LPDDR4 FPGA: 256MB DDR3	ARM: 8GB eMMC FPGA: 32MB QSPI FLASH	32MB QSPI FLASH	MXM 314PIN	-40°C~+85°C	45mm x 82mm	Linux	MYD-JX8MMA7-8E2D-32Q256D-160-I
MYC-JX8MMA7-8E2D-32Q256D-180-C	ARM: MIMX8MM6DVTLZAA FPGA: XC7A25T-2CSG325C	4*Cortex-A53@1.8GHz+ Cortex-M4@400MHz FPGA: 23K					0°C~+70°C			MYD-JX8MMA7-8E2D-32Q256D-180-C

Peripherals/Interfaces

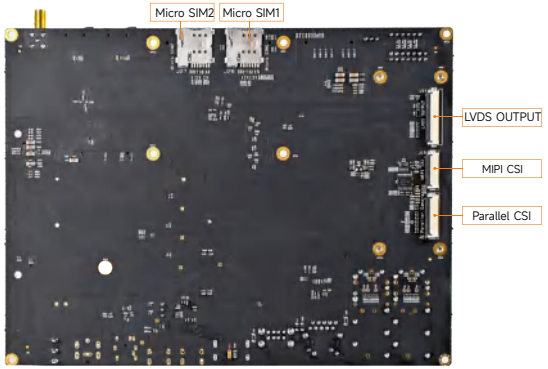
Communications	RGMII, 2×USB2.0, 4×UART, 2×SPI, 2×I2C, 3×GTP
Multimedia	MIPI DSI, MIPI CSI, 3×SAI
Others	JTAG

Key Applications

Data Acquisition | Medical Equipment | Industrial Control | Industrial Gateway

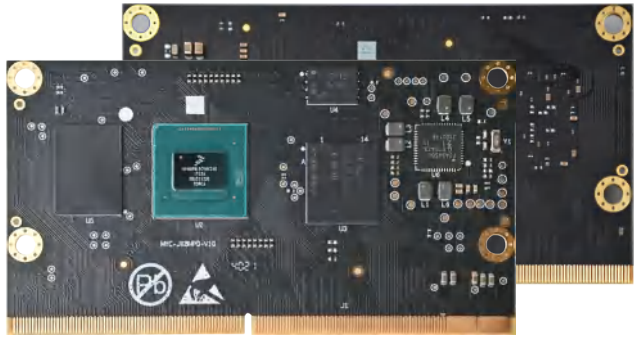


MYD-JX8MMA7 Development Board Top-view



MYD-JX8MMA7 Development Board Bottom-view

NXP | MYC-JX8MPQ



- NXP i.MX 8M Plus Processor, 4*Cortex-A53@1.6GHz + Cortex-M7@800MHz
- 2.3 TOPS NPU for Extensive AI/ML Capabilities; 800MHz Audio DSP, Dual Camera Interfaces (ISP), 3D GPU
- LPDDR4, eMMC, QSPI Flash; 2x USB3.0, 2x Gigabit Ethernet, 2x CAN FD, 4x UART, 3x SPI, 6x I2C
- 45mm x 82mm; MXM Package, 314-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-JX8MPQ-8E2D-160-I	MIMX8ML8CVNKZAB	4×Cortex-A53@1.6GHz +Cortex-M7@800MHz	2GB LPDDR4	8GB eMMC	32MB QSPI FLASH	MXM 314PIN	-40°C~+85°C	45mm x 82mm	Linux	MYD-JX8MPQ-8E2D-160-I
MYC-JX8MPQ-8E4D-160-I			4GB LPDDR4							MYD-JX8MPQ-8E4D-160-I

Peripherals/Interfaces

Communications	2×RGMII, PCIE3.0, 2×USB3.0, 2×CAN FD, 4×UART, 3×SPI, 6×I2C
Multimedia	HDMI, MIPI-DSI, LVDS, 2×MIPI CSI, 6×SAI
Others	JTAG

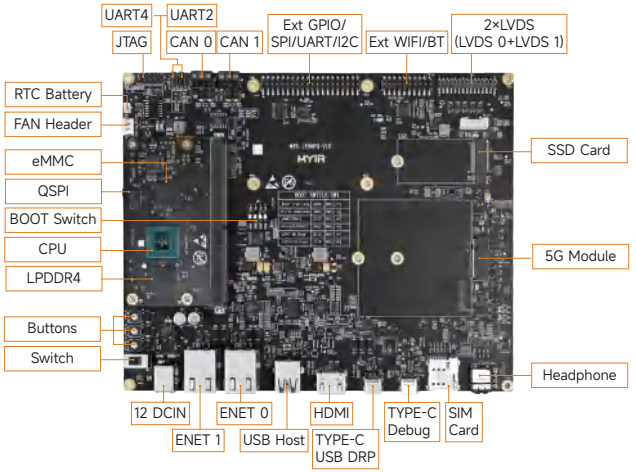
Key Applications

HMI

High-performance AI Devices

Industrial Computers

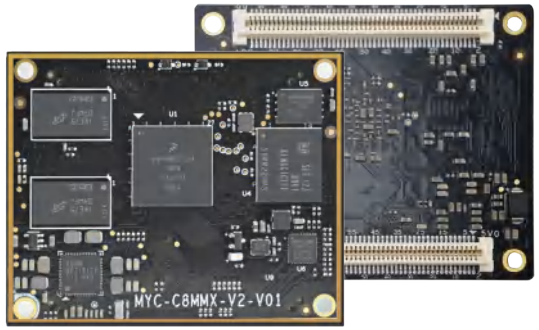
Edge Computing



MYD-JX8MPQ Development Board Top-view

MYD-JX8MPQ Development Board Bottom-view

NXP | MYC-C8MMX-V2



- NXP i.MX 8M Mini Processor, 4*Cortex-A53@1.8GHz + Cortex-M7@400MHz
- DDR4, eMMC, QSPI Flash, On-board Gigabit Ethernet PHY
- 2x USB2.0, Gigabit Ethernet, PCIE2.0, 4x UART, 3x SPI, 3x I2C
- 49mm x 60mm; 200-pin Board-to-Board Connectors; 0°C~+70°C Commercial; -40°C~+85°C Industrial
- Linux / Android OS

Part Selections (Other Configurations can be Customized for Mass Production)

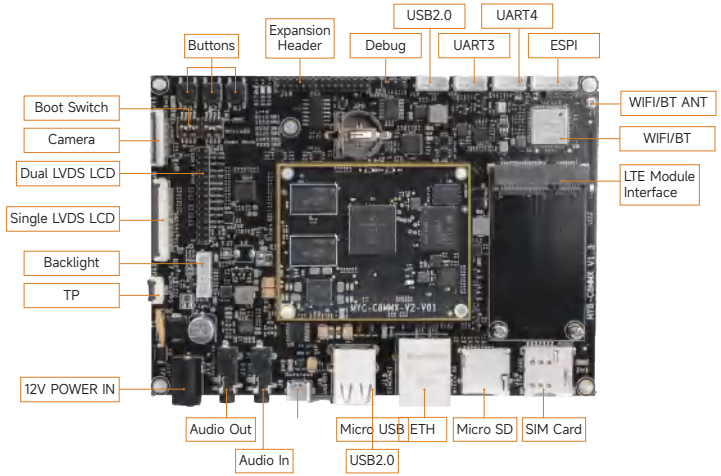
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C8MMQ6-V2-8E2D-180-C	MIMX8MM6DVTLZAA	4×Cortex-A53@1.8GHz +Cortex-M4@400MHz	2GB DDR4	8GB eMMC	Ethernet PHY 32MB QSPI FLASH	B2B 200PIN	0°C~+70°C	49mm × 60mm	Linux Android	MYD-C8MMQ6-V2-8E2D-180-C
MYC-C8MMQ6-V2-8E2D-160-I	MIMX8MM6CVTKZAA	4×Cortex-A53@1.6GHz +Cortex-M4@400MHz					-40°C~+85°C			MYD-C8MMQ6-V2-8E2D-160-I

Peripherals/Interfaces

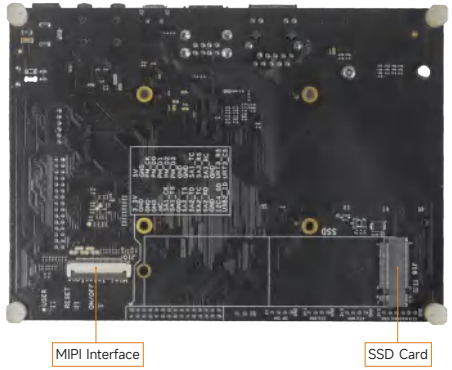
Communications	RGMII, PCIE2.0, 2×USB2.0, 4×UART, 3×SPI, 3×I2C
Multimedia	MIPI DSI, MIPI CSI, 5×SAI
Others	JTAG

Key Applications

Commercial HMI | Medical Device | Industrial Control | Artificial Intelligence



MYD-C8MMX-V2 Development Board Top-view



MYD-C8MMX-V2 Development Board Bottom-view

NXP | MYC-Y6ULX-V2

- NXP i.MX 6UL/i.MX 6ULL Processor, Cortex-A7@528MHz
- DDR3, Nand FLASH/eMMC, On-board Gigabit Ethernet PHY
- 2x USB2.0, 2x 10/100Mbps Ethernet, 2x CAN, 8x UART, 4x SPI, 4x I2C
- 37mm x 39mm; LCC Package, 140-pin; 0°C~+70°C Commercial; -40°C~+85°C Industrial;
- Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

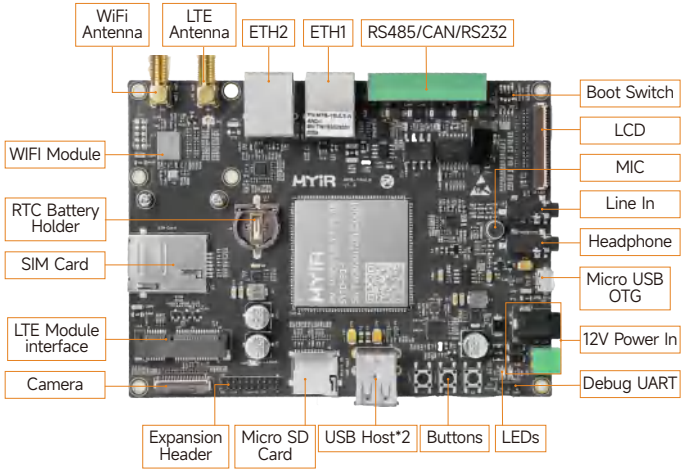
SOM Part Number	CPU	CPU CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-Y6ULY2-V2-256N256D-50-C	MCIMX6Y2CVM05AB	Cortex-A7@528MHz	256MB DDR3	256MB Nand FLASH	Ethernet PHY	LCC 140PIN	0°C~+70°C	37mm x 39mm	Linux	MYD-Y6ULY2-V2-256N256D-50-C
MYC-Y6ULY2-V2-256N256D-50-I							-40°C~+85°C			MYD-Y6ULY2-V2-256N256D-50-I
MYC-Y6ULY2-V2-4E512D-50-C			512MB DDR3	4GB eMMC			0°C~+70°C			MYD-Y6ULY2-V2-4E512D-50-C
MYC-Y6ULY2-V2-4E512D-50-I							-40°C~+85°C			MYD-Y6ULY2-V2-4E512D-50-I
MYC-Y6ULG2-V2-256N256D-50-I	MCIMX6G2CVM05AB		256MB DDR3	256MB Nand FLASH						MYD-Y6ULG2-V2-256N256D-50-I

Peripherals/Interfaces

Communications	2×RMII, 2×CAN, 2×USB2.0, 8×UART, 4×SPI, 4×I2C
Multimedia	RGB, Parallel CSI , 3×I2S
Others	2×12bit 10ch ADC, JTAG

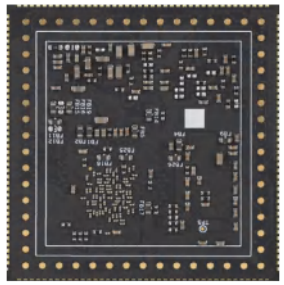
Key Applications

Charging Pile | HMI | Industrial Control | Medical Device



MYD-Y6ULX-V2 Development Board Top-view

TEXAS INSTRUMENTS | MYC-YM62X



- TI AM62x Processor, 1/2/4x Cortex-A53@1.4GHz + Cortex-M4F@400MHz
- DDR4, eMMC, EEPROM, PMIC
- 3D GPU (Only for AM625), full-HD dual-display support
- 2x Display Controllers, 2x USB2.0, 2x Gigabit Ethernet, 3x CAN-FD, 1x GPMC
- 43mm x 45mm; LCC + LGA Package, 164-pin + 58-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

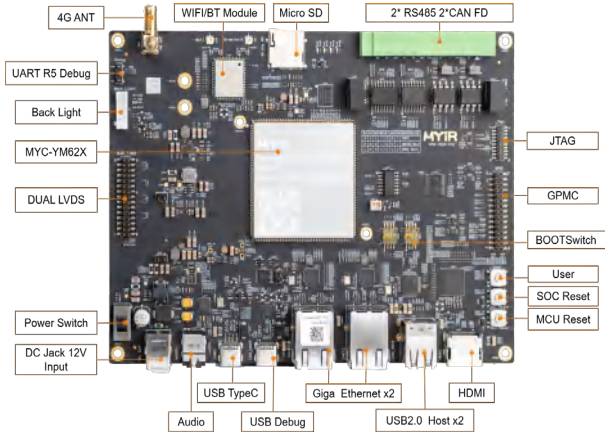
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YM6254-8E2D-140-I	AM6254ATCGGAALW	4×Cortex-A53@1.4GHz+ Cortex-M4F@400MHz	2GB DDR4	8GB eMMC	32Kbit EEPROM	LCC+LGA 222PIN	-40°C~+85°C	43mm x 45mm	Linux	MYD-YM6254-8E2D-140-I
MYC-YM6252-8E1D-140-I	AM6252ATCGGAALW	2×Cortex-A53@1.4GHz+ Cortex-M4F@400MHz	1GB DDR4							MYD-YM6252-8E1D-140-I
MYC-YM6231-8E1D-140-I	AM6231ASGGGAALW	Cortex-A53@1.0GHz+ Cortex-M4F@400MHz	1GB DDR4							MYD-YM6231-8E1D-140-I

Peripherals/Interfaces

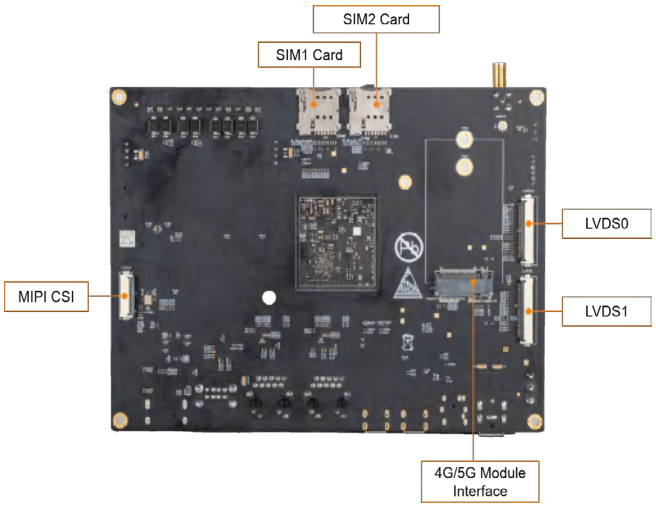
Communications	2×RGMII, 2×USB 2.0, 9×URAT, 3×CAN FD, 4×I2C, 5×SPI
Multimedia	2×LVDS, 1×RGB, 1×MIPI CSI, 3×MCASP
Others	1×GPMC, 1×JTAG

Key Applications

Industrial HMI | Medical Device | Industrial Control | Energy & Power



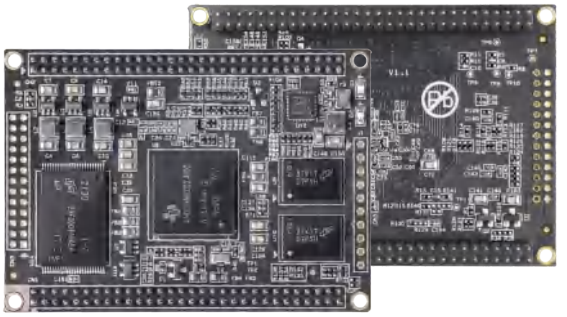
MYD-YM62X Development Board Top-view



MYD-YM62X Development Board Bottom-view

TEXAS INSTRUMENTS | MYC-C335X-V4

- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash, Gigabit Ethernet PHY
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN
- 70mm x 50mm; DIP Package, 2x 60-pin; -40°C~+85°C Industrial; Linux



Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C3352-V4-256N256D-80-I	AM3352BZCZD80	Cortex-A8@800MHz	256MB DDR3	256MB Nand FLASH	Ethernet PHY 32Kbit EEPROM	DIP 2×60PIN	-40°C~+85°C	70mm × 50mm	Linux	MYD-C3352-V4-256N256D-80-I
MYC-C3352-V4-512N512D-80-I			512MB DDR3	512MB Nand FLASH						MYD-C3352-V4-512N512D-80-I
MYC-C3352-V4-512N512D-80-C							0°C~+70°C			MYD-C3352-V4-512N512D-80-C
MYC-C3358-V4-256N256D-100-I	AM3358BZCZA100	Cortex-A8@1.0GHz	256MB DDR3	256MB Nand FLASH			-40°C~+85°C			MYD-C3358-V4-256N256D-100-I
MYC-C3358-V4-512N512D-100-I			512MB DDR3	512MB Nand FLASH						MYD-C3358-V4-512N512D-100-I
MYC-C3358-V4-512N512D-100-C							0°C~+70°C			MYD-C3358-V4-512N512D-100-C

Peripherals/Interfaces

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×McASP
Others	12bit 8ch ADC, JTAG

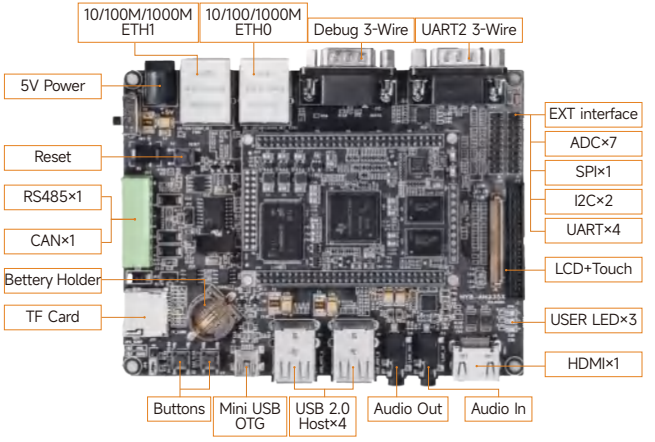
Key Applications

Charging PileBilling Control Unit

Medical Equipment

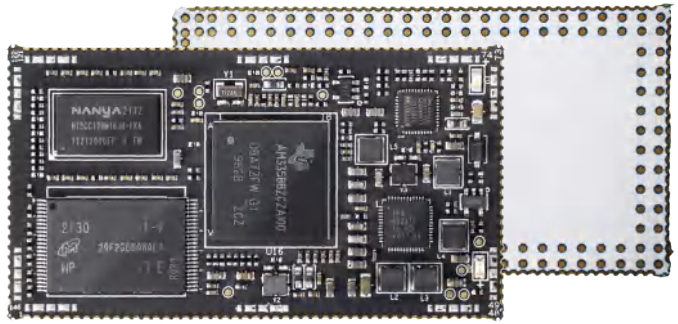
Industrial Control

Gaming Peripherals



MYD-C335X-V4 Development Board Top-view

TEXAS INSTRUMENTS | MYC-Y335X-V2



- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash, Gigabit Ethernet PHY, PMIC
- 6x UART, 2x USB 2.0, 2x Gigabit Ethernet, 2x CAN
- 65mm x 35mm; LCC Package, 146-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-Y3352-V2-256N256D-80-I	AM3352BZCZD80	Cortex-A8@800MHz	256MB DDR3	256MB Nand FLASH	Ethernet PHY 32Kbit EEPROM	LCC 146PIN	-40°C~+85°C	65mm x 35mm	Linux	MYD-Y3352-V2-256N256D-80-I
MYC-Y3358-V2-256N256D-100-I	AM3358BZCZA100	Cortex-A8@1.0GHz								MYD-Y3358-V2-256N256D-100-I

Peripherals/Interfaces

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×McASP
Others	2×12bit 8ch ADC, JTAG

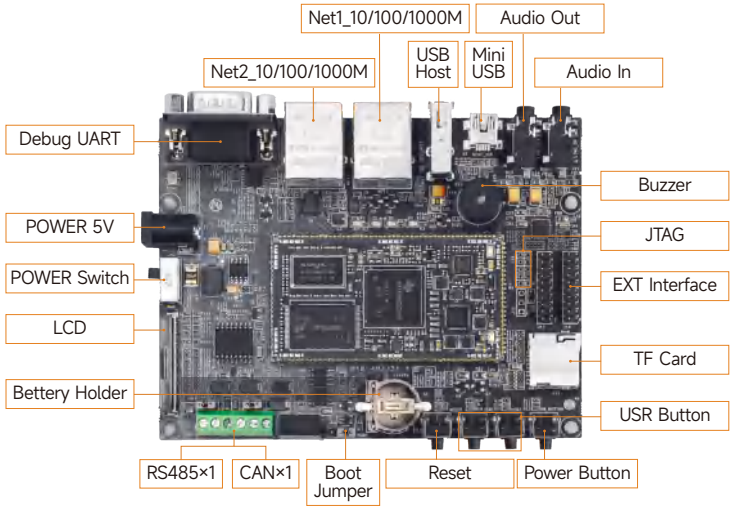
Key Applications

Charging PileBilling Control Unit

Medical Equipment

Industrial Control

Gaming Peripherals



MYD-Y335X-V2 Development Board Top-view

MYC-J335X-V2

- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash, Gigabit Ethernet PHY, PMIC
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN, 2x SPI
- 67mm x 45mm; MXM Package, 200-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-J3352-V2-256N256D-80-I	AM3352BZCZD80	Cortex-A8@800MHz	256MB DDR3	256MB Nand FLASH	Ethernet PHY 32Kbit EEPROM	MXM 200PIN	-40°C~+85°C	67mm x 45mm	Linux	MYD-J3352-V2-256N256D-80-I
MYC-J3358-V2-256N256D-100-I	AM3358BZCZA100	Cortex-A8@1.0GHz								MYD-J3358-V2-256N256D-100-I

Peripherals/Interfaces

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×McASP
Others	12bit 8ch ADC, JTAG

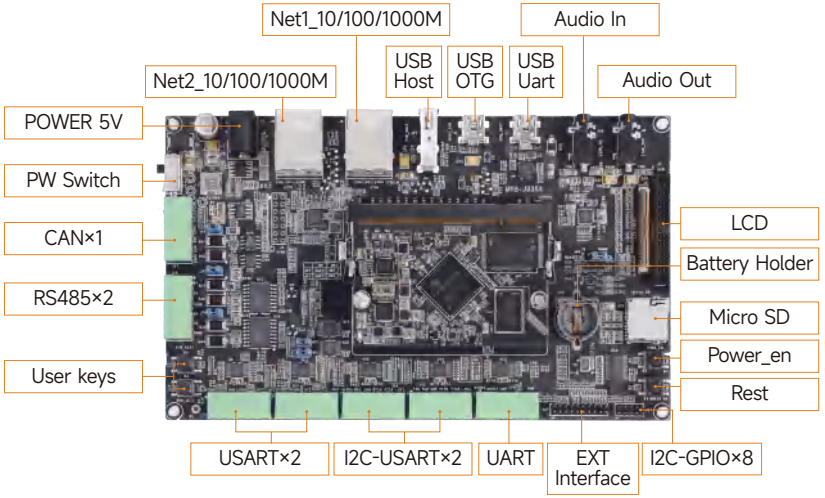
Key Applications

Charging PileBilling Control Unit

Medical Equipment

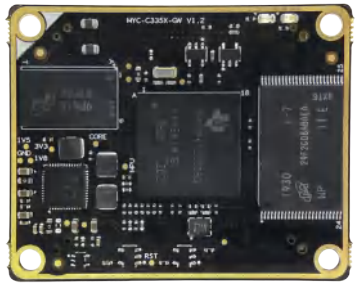
Industrial Control

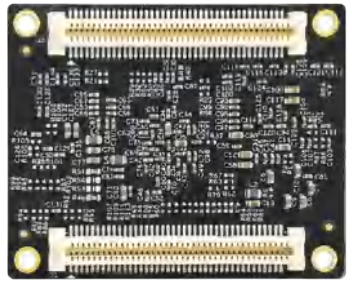
Gaming Peripherals



MYD-J335X-V2 Development Board Top-view

TEXAS INSTRUMENTS | MYC-C335X-GW





- Up to 1GHz TI AM335x Cortex-A8 processors
- DDR3, Nand Flash/eMMC, EEPROM, PMIC
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN
- 50mm x 40mm; B2B Package, 2x 80-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

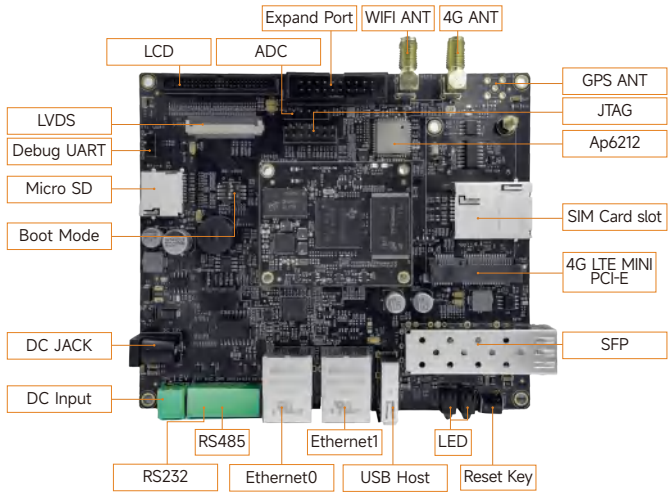
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C3354-256N256D-80-I-GW	AM3354BZCZD80	Cortex-A8@800MHz	256MB DDR3L	256MB Nand Flash	32Kbit EEPROM	B2B 2×80PIN	-40°C~+85°C	50mm x 40mm	Linux	MYD-C3354-256N256D-80-I-GW
MYC-C3354-4E512D-80-I-GW			512MB DDR3L	4GB eMMC						MYD-C3354-4E512D-80-I-GW

Peripherals/Interfaces

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×McASP
Others	12bit 8ch ADC, JTAG

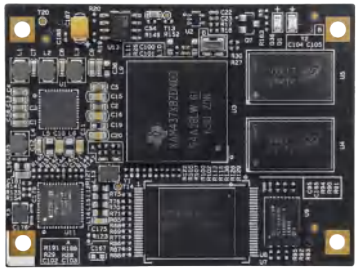
Key Applications

Industrial Gateway | HMI | Medical Equipment | Industrial Control



MYD-C335X-GW Development Board Top-view

MYC-C437X-V2



- Up to 1GHz TI AM437x Cortex-A9 Processor
- DDR3, eMMC, EEPROM, Gigabit Ethernet PHY, PMIC
- 6x UART, 2x USB2.0, 2x Gigabit Ethernet, 2x CAN, 2x SPI, 3x I2C, 2x Parallel Camera Interfaces
- 45mm x 60mm; B2B Package, 200-pin; -40°C~+85°C Industrial; Linux

Part Selections (Other Configurations can be Customized for Mass Production)

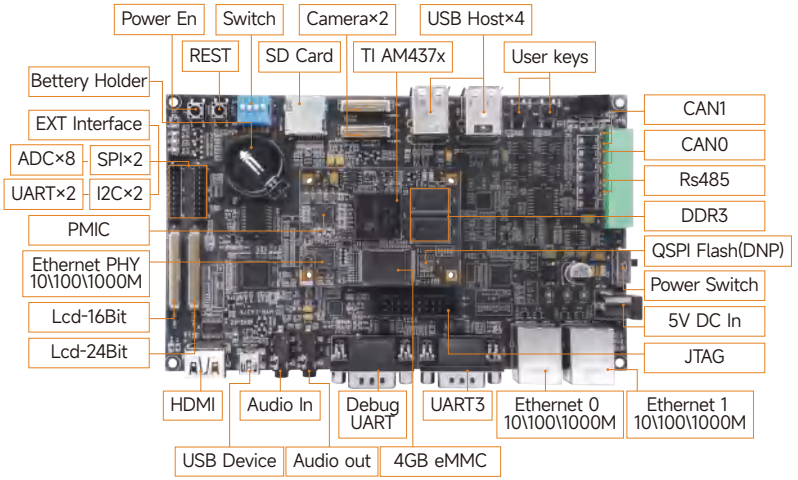
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C4378-V2-4E512D-100-C	AM4378BZDND100	Cortex-A9@1.0GHz	512MB DDR3	4GB eMMC	Ethernet PHY 32KB EEPROM	B2B 200PIN	0°C~+70°C	45mm x 60mm	Linux	MYD-C4378-V2-4E512D-100-C
MYC-C4378-V2-4E512D-100-I							-40°C~+85°C			MYD-C4378-V2-4E512D-100-I

Peripherals/Interfaces

Communications	2×RGMII, 2×CAN, 2×USB2.0, 6×UART, 2×SPI, 3×I2C
Multimedia	RGB, 2×Parallel CSI, 2×McASP
Others	2×12bit 8ch ADC, JTAG

Key Applications

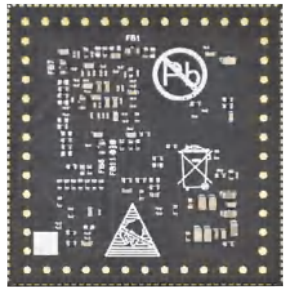
Industrial HMI | Medical Equipment | Industrial Control | Code Scanner



MYD-C437X-V2 Development Board Top-view

RENESAS | MYC-YG2UL

- RENESAS RZ/G2UL Processor, 64-bit MPU, Cortex-A55@1.0GHz + Cortex-M33@200MHz
- DDR3L, eMMC, EEPROM
- Camera Interface, Display Interface, USB2.0, CAN-FD, Dual Gigabit Ethernet
- 37mm x 39mm; LCC + LGA Package, 190-pin; -40°C~+85°C Industrial; Linux OS



Part Selections (Other Configurations can be Customized for Mass Production)

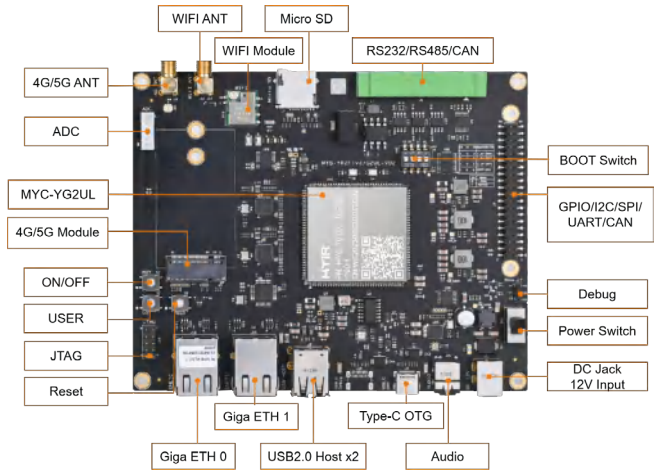
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YG2UL-4E512D-100-I	R9A07G043U11GBG	Cortex-A55@1.0GHz+ Cortex-M33@200MHz	512MB DDR3	4GB eMMC	32KBit EEPROM	LCC+LGA 190PIN	-40°C~+85°C	37mm x 39mm	Linux OpenWrt	MYD-YG2UL-4E512D-100-I

Peripherals/Interfaces

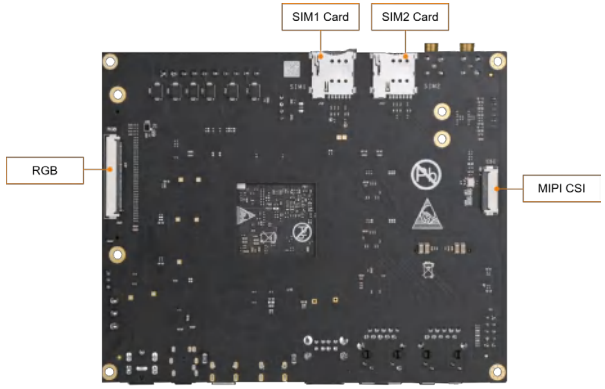
Communications	2×RGMII, 2×CAN FD, 2×USB2.0, 7×UART, 3×SPI, 4×I2C
Multimedia	RGB, MIPI CSI, 4×SSI
Others	12-bit 2-ch ADC, JTAG

Key Applications

Charging Pile | Motion Controller | Engineering Machinery | Medical Device



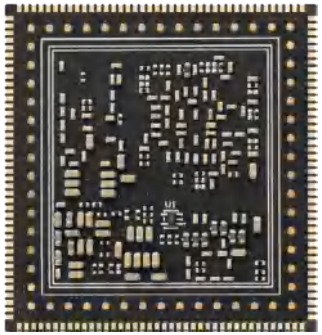
MYD-YG2UL Development Board Top-view



MYD-YG2UL Development Board Bottom-view

RENESAS | MYC-YG2LX

- RENESAS RZ/G2L Processor, 2x Cortex-A55@1.2GHz + Cortex-M33@200MHz
- Integrated 3D Graphics engine and video CODEC engine (H.264)
- Rich Multimedia Interfaces: MIPI-DSI / RGB / MIPI-CSI / Parallel CSI
- 43mm x 45mm; LCC + LGA Package, 222-pin; -40°C~+85°C Industrial; Linux / Ubuntu OS



Part Selections (Other Configurations can be Customized for Mass Production)

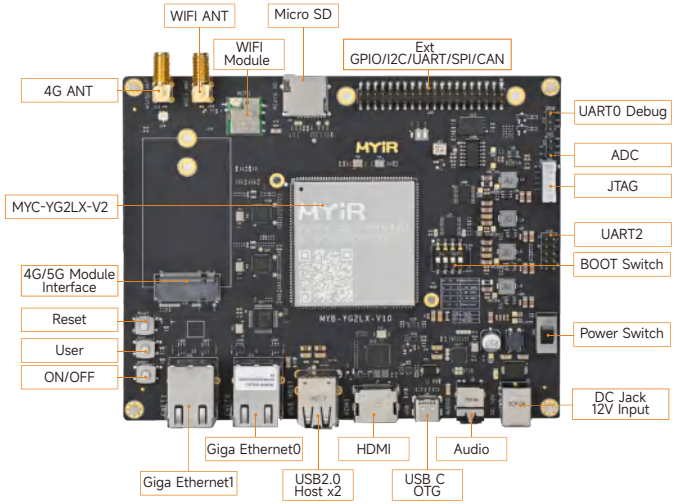
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YG2L23-8E1D-120-I	R9A07G044L23GBG	2×Cortex-A55@1.2GHz+ Cortex-M33@200MHz	1GB DDR4	8GB eMMC	32KB EEPROM	LCC+LGA 222PIN	-40°C~+85°C	43mm x 45mm	Linux Ubuntu	MYD-YG2L23-8E1D-120-I
MYC-YG2L23-8E2D-120-I			2GB DDR4							MYD-YG2L23-8E2D-120-I

Peripherals/Interfaces

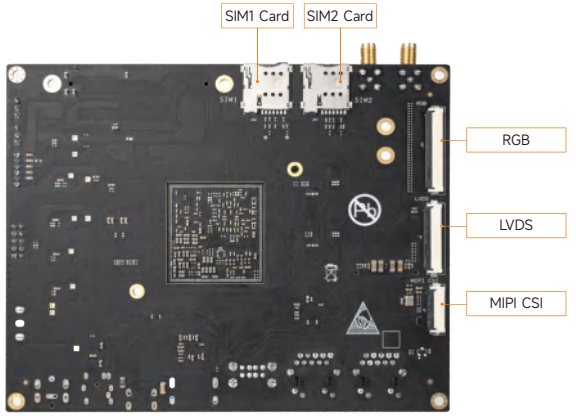
Communications	2×RGMII, 2×CAN FD, 2×USB2.0, 7×UART, 3×SPI, 4×I2C
Multimedia	RGB, MIPI DSI, Parallel CSI, MIPI CSI, SSI, SRC
Others	12-bit 8-ch ADC, JTAG

Key Applications

Industrial HMI | Industrial Gateway | Industrial Control | Energy & Power



MYD-YG2LX Development Board Top-view



MYD-YG2LX Development Board Bottom-view

MYC-C7Z010/20-V2

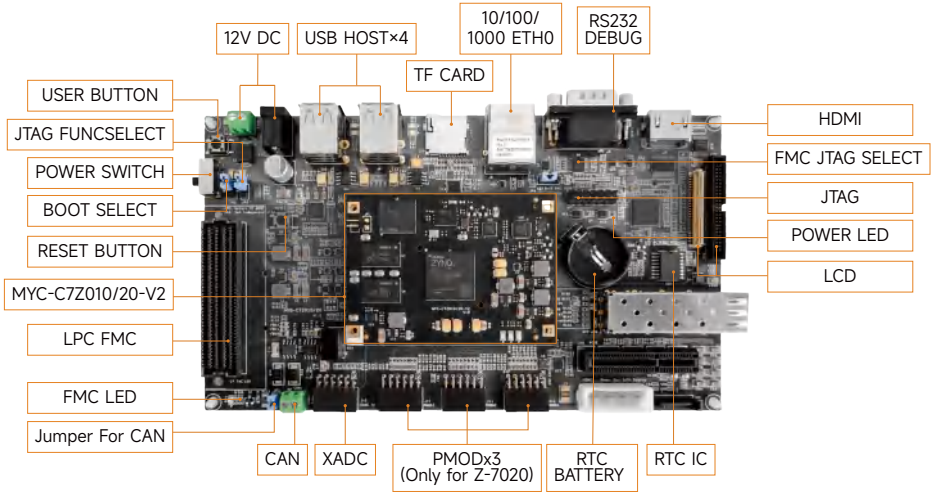
- Xilinx XC7Z010/20 Processor, 2x Cortex-A9@667/766MHz+Artix 7 FPGA
- DDR3, eMMC, QSPI Flash
- On-board Gigabit Ethernet PHY
- 75mm x 55mm; B2B Package, 2x140-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C7Z010-V2-4E1D-667-I	xc7z010-1clg400	2×Cortex-A9@667Hz +Atrix 7 FPGA (28K)	1GB DDR3	4GB eMMC	32MB QSPI Flash Ethernet PHY USB PHY	B2B 2×140PIN	-40°C~+85°C	75mm × 55mm	Linux	MYD-C7Z010-V2-4E1D-667-I
MYC-C7Z020-V2-4E1D-766-I	xc7z020-2clg400	2×Cortex-A9@766Hz +Atrix 7 FPGA (85K)								MYD-C7Z020-V2-4E1D-766-I
MYC-C7Z010-V2-4E1D-667-C	xc7z010-1clg400	2×Cortex-A9@667Hz +Atrix 7 FPGA (28K)					0°C~+70°C			MYD-C7Z010-V2-4E1D-667-C
MYC-C7Z020-V2-4E1D-766-C	xc7z020-2clg400	2×Cortex-A9@766Hz +Atrix 7 FPGA (85K)								MYD-C7Z020-V2-4E1D-766-C

Peripherals/Interfaces

Communications	RGMII, USB2.0, CAN, 2×SPI, 2x I2C, XADC
FPGA Expansion IO	141PIN (FPGA_XC7020) , 114PIN (FPGA_XC7010)



MYD-C7Z010/20-V2 Development Board Top-view

Key Applications

Automotive | Medical Device | Industrial Control | Communication Systems

MYC-Y7Z010/20-V2

- Xilinx XC7Z010/20 Processor, 2x Cortex-A9@667/766MHz+Artix 7 FPGA
- DDR3, eMMC, QSPI Flash
- On-board Gigabit Ethernet PHY
- 75mm x 50mm; LCC Package, 180-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

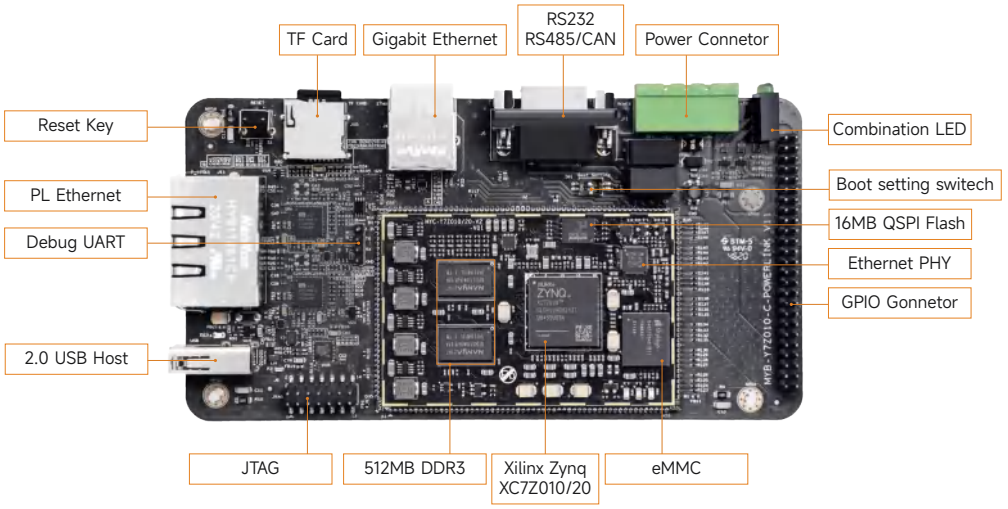
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-Y7Z010-V2-4E512D-667-I	xc7z010-1clg400	2*Cortex-A9@667Hz +Atrix 7 FPGA (28K)	512MB DDR3	4GB eMMC	16MB QSPI Flash Ethernet PHY	LCC 180PIN	-40°C~+85°C	75mm × 50mm	Linux	MYD-Y7Z010-V2-4E1D-667-I
MYC-Y7Z020-V2-4E512D-766-I	xc7z020-2clg400	2*Cortex-A9@766Hz +Atrix 7 FPGA (85K)								MYD-Y7Z020-V2-4E1D-766-I

Peripherals/Interfaces

Communications	RGMII, USB2.0, CAN, 2×SPI, 2× I2C, JTAG
FPGA Expansion IO	Expandable 121PIN

Key Applications

Automotive | Medical Device | Industrial Control | Artificial Intelligence (AI)



MYD-Y7Z010/20-V2 Development Board Top-view

MYC-C7Z015

- Xilinx XC7Z015 Processor, 2x Cortex-A9@766MHz+Artix 7 FPGA
- DDR3, eMMC, QSPI Flash
- On-board Gigabit Ethernet PHY
- 75mm x 55mm; B2B Package, 2x140-pin; -40°C~+85°C Industrial; Linux OS

Part Selections (Other Configurations can be Customized for Mass Production)

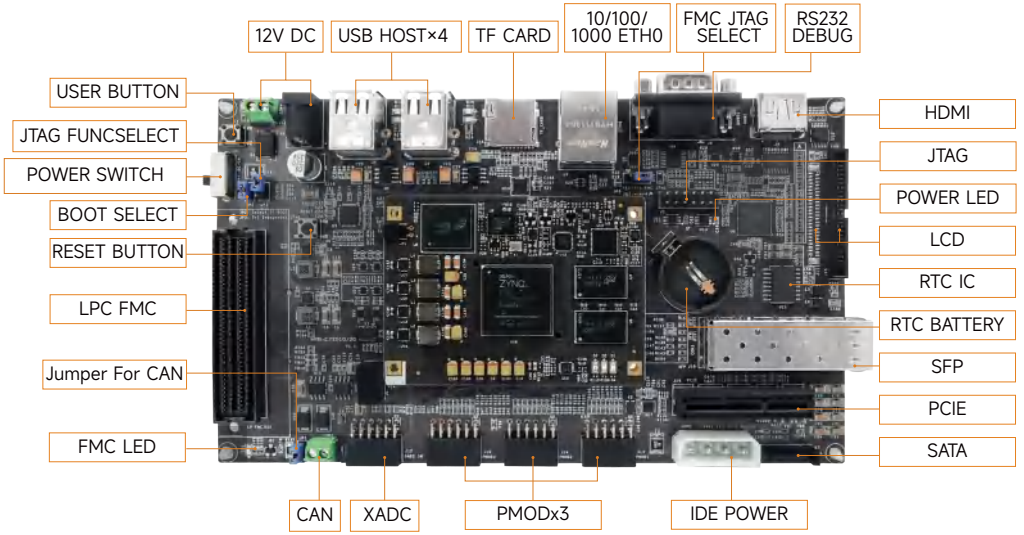
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-C7Z015-4E1D-766-I	xc7z015-2clg485	2×Cortex-A9@766Hz +Atrix 7 FPGA (74K)	1GB DDR3	4GB eMMC	32MB QSPI Flash Ethernet PHY USB PHY	B2B 2×140PIN	-40°C~+85°C	75mm × 55mm	Linux	MYD-C7Z015-4E1D-766-I

Peripherals/Interfaces

Communications	RGMII, USB2.0, CAN, 2×SPI, 2×I2C, 2×XADC, SFP, PCIE, SATA
FPGA Expansion IO	137PIN (FPGA_XC7015)

Key Applications

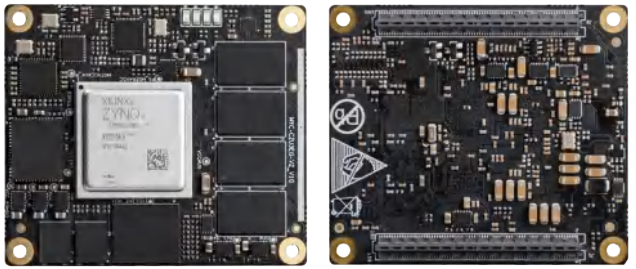
Automotive | Medical Device | Industrial Control | Communication Systems



MYD-C7Z015 Development Board Top-view

MYC-CZU3EG/4EV/5EV-V2

- Zynq UltraScale+ ZU3EG /ZU4EV /ZU5EV MPSoC, 4x Cortex-A53@1.2GHz+2x Cortex-R5@600MHz
- DDR4, eMMC, QSPI Flash
- USB 3.0, Gigabit Ethernet, CAN, TF, DP, PCIe, SATA, HDMI, LCD
- 60mm x 52mm; B2B Package, 2x160-pin; 0°C~+70°C Commercial; Linux OS

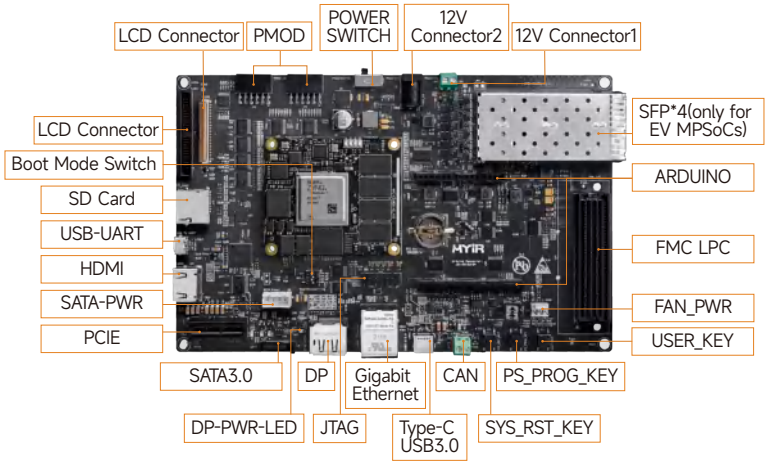


Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-CZU3EG-V2-4E4D-1200-C	XCZU3EG-1SFVC784	ARM: 4×A53@1200MHz+2×R5@533MHz + UltraScale+ FPGA 154K	4GB DDR4	4GB eMMC	128MB QSPI Flash Ethernet PHY USB PHY	B2B 2×160PIN	0°C~+70°C	60mm × 52mm	Linux	MYD-CZU3EG-V2-4E4D-1200-C
MYC-CZU4EV-V2-4E4D-1200-I-FAN	XCZU4EV-2SFVC784	ARM: 4×A53@1200MHz+2×R5@533MHz + UltraScale+ FPGA 192K					-40°C~+85°C			MYD-CZU4EV-V2-4E4D-1200-C
MYC-CZU5EV-V2-4E4D-1200-I-FAN	XCZU5EV-2SFVC784	ARM: 4×A53@1200MHz+2×R5@533MHz + UltraScale+ FPGA 256K								MYD-CZU5EV-V2-4E4D-1200-C

Peripherals/Interfaces

Communications	RGMII, CAN, USB3.0, USB_UART, 2×PMOD, PCIE2.0, DP, SATA3.0, 4×SFP (Only for 4EV/5EV)
FPGA Expansion IO	156PIN (FPGA)



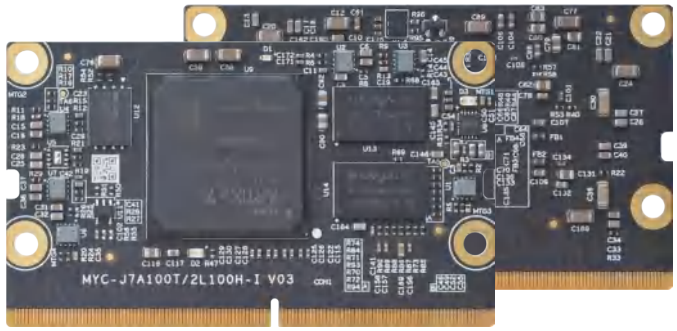
MYD-CZU3EG/4EV/5EV-V2 Development Board Top-view

Key Applications

Data Center | Medical Device | Industrial Control | Automotive

MYC-J7A100T

- AMD/Xilinx XC7A100T Artix-7 FPGA (XC7A100T-2FGG484I)
- DDR3, QSPI FLASH, EEPROM
- Supports Development by Xilinx's Vivado Design Suite
- 69.6mm x 40mm; MXM Package, 260-pin; -40°C~+85°C Industrial



Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-J7A100T-32Q512D-I	XC7A100T-2FGG484I	-	512MB DDR3	32MB QSPI FLASH	32KB EEPROM	MXM 260PIN	-40°C~+85°C	69.6mm x 40mm	Xilinx's Vivado Design Suite	MYD-J7A100T-32Q512D-I

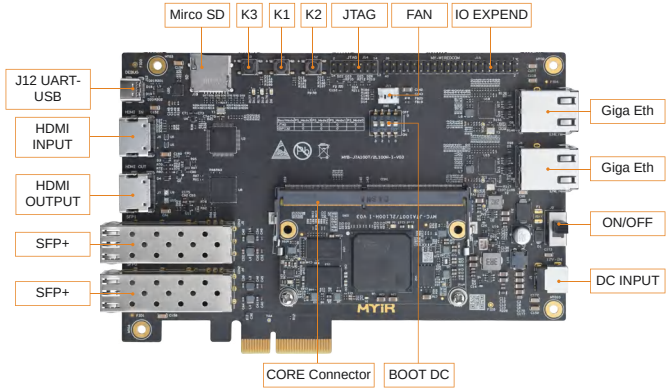
Signals Routed to Pins

0.5mm pitch MXM Gold-finger-edge-card Expansion Interface

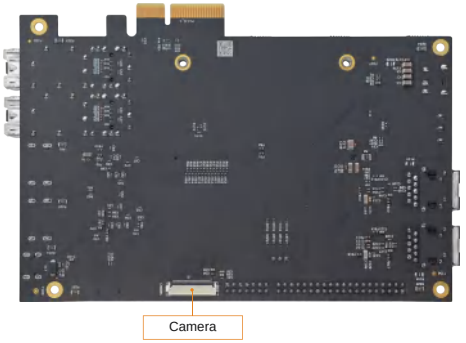
Item	Number of I/Os	Description
Bank13	35	There are 178 I/Os in total, which are defined according to different requirements. Signal lines with the same function are located on the same bank.
Bank14	45	
Bank15	48	
Bank16	50	
MGTP	20	High-Speed Serial Interfaces
JTAG	4	JTAG Debug

Key Applications

Communication | Computing | Industrial Control | Automotive



MYD-J7A100T Development Board Top-view



MYD-J7A100T Development Board Bottom-view

ALLWINNER | MYC-YT507H

- Allwinner T507-H processor, 4x Cortex-A53@1.5GHz
- LPDDR4, eMMC, EEPROM, PMIC
- Supports 4K@60FPS H.265 video decoding and 4K@25FPS H.264 video encoding
- Supports different display in dual screens, MIPI CSI and DVP camera inputs
- 43mm x 45mm; LCC + LGA Package, 164-pin + 58-pin; -40°C~+85°C Industrial; Linux / Android / Ubuntu

Part Selections (Other Configurations can be Customized for Mass Production)

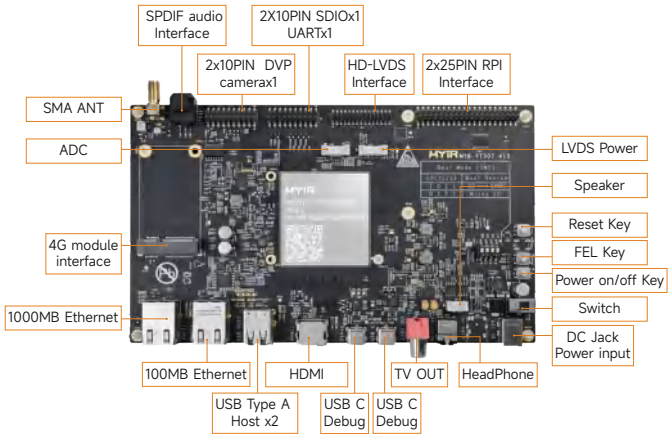
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YT507H-8E1D-150-I	T507H	4×Cortex-A53@1.5GHz	1GB LPDDR4	8GB eMMC	32Kbit EEPROM	LCC+LGA 222PIN	-40°C~+85°C	43mm x 45mm	Linux Android Ubuntu	MYD-YT507H-8E1D-150-I
MYC-YT507H-8E2D-150-I			2GB LPDDR4							MYD-YT507H-8E2D-150-I

Peripherals/Interfaces

Communications	RGMII, 4×USB2.0, 6×UART, 2×SDIO, 2×SPI, 4×I2C, 6×PWM, 5×ADC
Multimedia	HDMI, 2×LVDS, RGB24, TV CVBS, Parallel CSI, MIPI CSI, 3×I2S, SPDIF

Key Applications

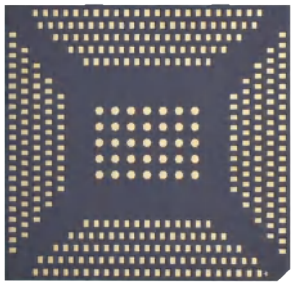
Commercial Display | Medical Equipment | Industrial Control | Intelligent Terminal



MYD-YT507H Development Board Top-view

MYD-YT507H Development Board Bottom-view

ALLWINNER | MYC-LT527



- Allwinner T527 processor, 4x Cortex-A55@1.8GHz + 4x Cortex-A55@1.4GHz + RISC-V@200MHz
- Up to 2 Tops NPU, LPDDR4, eMMC, EEPROM, PMIC
- G57 GPU, 4K encoding/decoding VPU, HiFi4 DSP, 4 to 6 camera inputs
- Multi video output interfaces: HDMI, DP, LVDS, MIPI-DSI, and RGB; Supports 4K+1080P dual-screen display
- 43mm x 45mm; LGA Package, 381-pin; -40°C~+85°C Industrial; Linux / Android / Ubuntu

Part Selections (Other Configurations can be Customized for Mass Production)

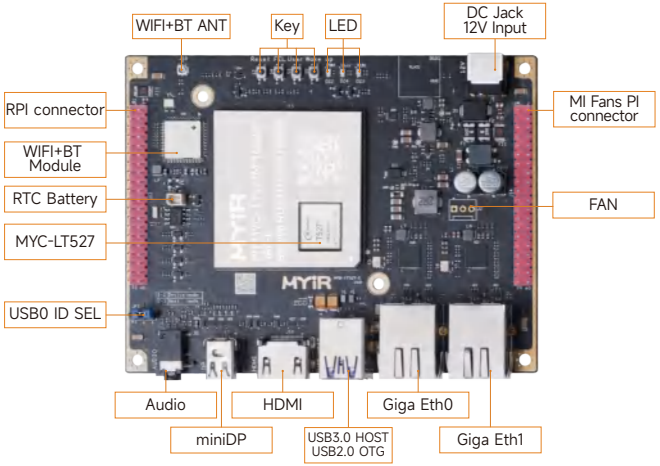
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC- LT527MN-16E2D-180-I-G	T527MN	4×Cortex-A55@1.8GHz +4×Cortex-A55@1.4GHz, RISC-V@200MHz, HIF14 600MHz, 2Tops NPU	2GB LPDDR4	16GB eMMC	32Kbit EEPROM	LGA 381PIN	-40°C~+85°C	43mm x 45mm	Linux Android Ubuntu	MYD- LT527MN-16E2D-180-I
MYC- LT527MN-32E4D-180-I-G			4GB LPDDR4	32GB eMMC						MYD- LT527MN-32E4D-180-I
MYC- LT527M-16E2D-180-I-G	T527M	4×Cortex-A55@1.8GHz +4×Cortex-A55@1.4GHz, RISC-V@200MHz	2GB LPDDR4	16GB eMMC						MYD- LT527M-16E2D-180-I
MYC- LT527M-16E2D-180-E							-20°C~+70°C			MYD- LT527M-16E2D-180-E

Peripherals/Interfaces

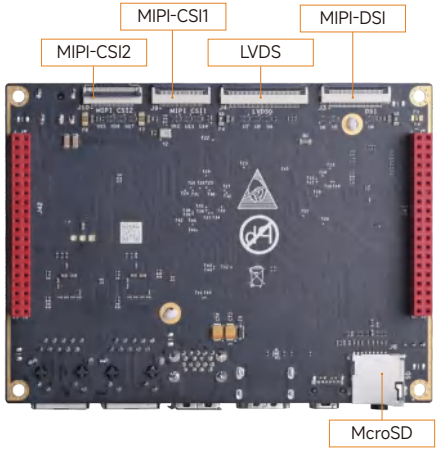
Communications	RGMII, 4×USB2.0, 6×UART, 2×SDIO, 2×SPI, 4×I2C, 6×PWM, 5×ADC
Multimedia	HDMI, 2×LVDS, RGB24, TV CVBS, Parallel CSI, MIPI CSI, 3×I2S, SPDIF

Key Applications

Commercial Display | Medical Equipment | Industrial Control | Intelligent Terminal



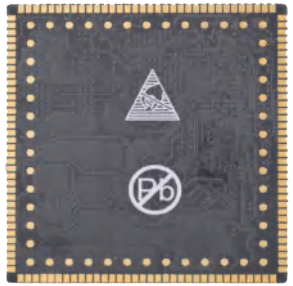
MYD-LT527 Development Board Top-view



MYD-LT527 Development Board Bottom-view

ALLWINNER | MYC-YT113i

- Allwinner T113-i Processor, 2x Cortex-A7@1.2GHz + RISC-V@800MHz
- DDR3, eMMC, EEPROM
- 1x Gigabit Ethernet, 2x USB2.0, 6x UART, 2x CAN, 8x PWM, 1x GPADC, 4x TPADC
- 37mm x 39mm; LCC + LGA Package, 140-pin + 50-pin; -40°C~+85°C Industrial; Linux



Part Selections (Other Configurations can be Customized for Mass Production)

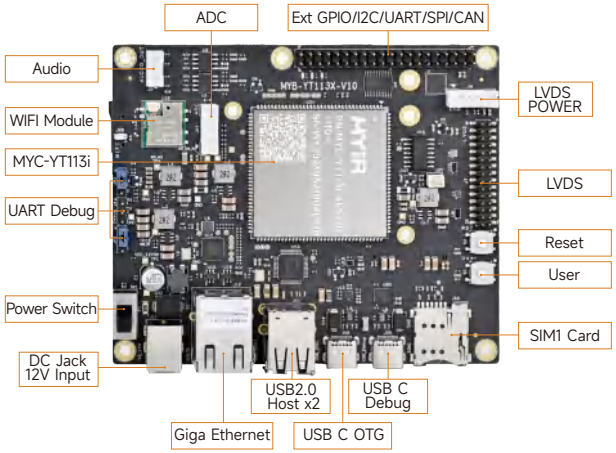
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YT113i-4E256D-110-I	T113-i	2×Cortex-A7@1.2G +RISC-V@800MHz	256MB DDR3	4GB eMMC	32Kbit EEPROM	LCC+LGA 140+50PIN	-40°C~+85°C	37mm x 39mm	Linux	MYD-YT113i-4E256D-110-I
MYC-YT113i-4E512D-110-I			512MB DDR3							MYD-YT113i-4E512D-110-I
MYC-YT113i-8E512D-110-I				8GB eMMC						MYD-YT113i-8E512D-110-I
MYC-YT113i-8E1D-110-I			1GB DDR3							MYD-YT113i-8E1D-110-I

Peripherals/Interfaces

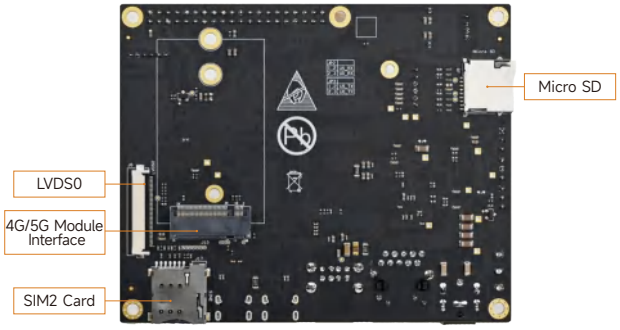
Communications	RGMII, 2×USB2.0, 6×UART, 2×CAN, SDIO, SPI, 4×I2C, 8×PWM
Multimedia	MIPI DSI, RGB DSI, Dual link LVDS, CVBS OUT, Parallel CSI, 2×I2S

Key Applications

Commercial Display | Medical Equipment | Industrial Control | Energy & Power



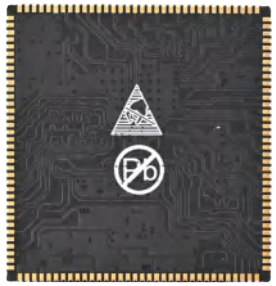
MYD-YT113i Development Board Top-view



MYD-YT113i Development Board Bottom-view

ALLWINNER | MYC-YT113X

- Allwinner T113-S3 Processor, 2x Cortex-A7@1.2GHz, with built-in 128MB DDR3
- Rich multimedia interfaces: MIPI-DSI / RGB / LVDS / Parallel CSI
- 6x UART, 2x USB2.0, 1x Gigabit Ethernet, 2x CAN
- 37mm x 39mm; LCC Package, 140-pin; -40°C~+85°C Industrial; Linux



Part Selections (Other Configurations can be Customized for Mass Production)

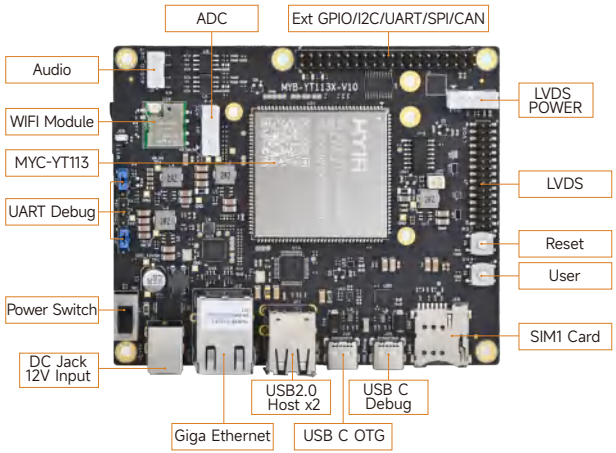
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-YT113S3-256N128D-110-I	T113-S3	2×Cortex-A7@1.2GHz	128MB DDR3	256MB Nand Flash	32Kbit EEPROM	LCC 140PIN	-40°C~+85°C	37mm x 39mm	Linux	MYD-YT113S3-256N128D-110-I
MYC-YT113S3-4E128D-110-I				4GB eMMC						MYD-YT113S3-4E128D-110-I

Peripherals/Interfaces

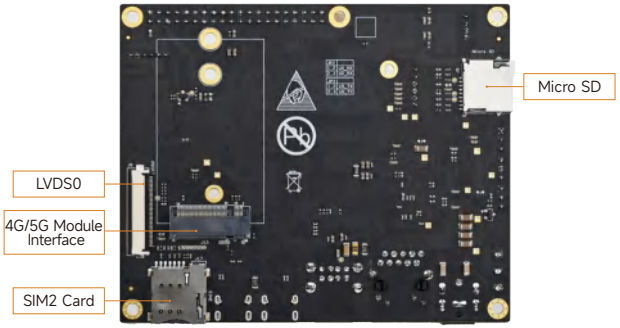
Communications	RGMII, 2×USB2.0, 6×UART, 2×CAN, SDIO, 2×SPI, 4×I2C, 8×PWM
Multimedia	MIPI DSI, RGB DSI, 2×LVDS, Parallel CSI, 2×I2S

Key Applications

Commercial Display | Medical Equipment | Industrial Control | Energy & Power



MYD-YT113X Development Board Top-view



MYD-YT113X Development Board Bottom-view

芯驰 SemiDrive | MYC-JD9360

- SemiDrive D9-Pro processor, 6x Cortex-A55@1.6GHz + Cortex-R5@800MHz + 0.8 Tops NPU
- Support dual display at 1080p resolution of different contents
- Support the third HMI display through Cortex-R5 co-processor control
- HD vision processing unit (VPU): H.264 encoding and decoding 4Kp30, H.265 decoding 4Kp30
- 82mm x 45mm; MXM Package, 314-pin; -40°C~+85°C Industrial; Linux / Ubuntu

Part Selections (Other Configurations can be Customized for Mass Production)

SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-JD9360-16E2D-160-I	D9-Pro	6×Cortex-A55@1.6GHz +Cortex-R5@800MHz +0.8Tops NPU	2GB LPDDR4	16GB eMMC	EEPROM	MXM 314PIN	-40°C~+85°C	82mm × 45mm	Linux Ubuntu	MYD-JD9360-16E2D-160-I

Peripherals/Interfaces

Communications	2×RGMII, 2×USB3.0, 2×PCIe3.0, 16×UART, 4×CAN FD, 2×SDIO, 8×SPI, 12×I2C, 8×PWM, 4×ADC
Multimedia	MIPI DSI, LVDS, MIPI CSI, Parallel CSI

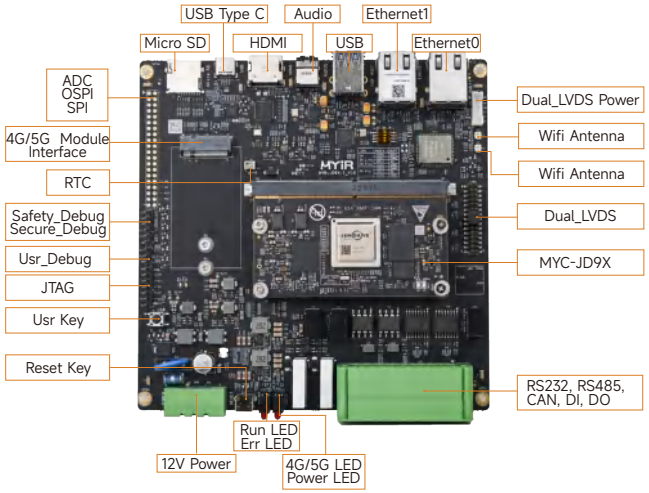
Key Applications

Construction Machinery T-BOX

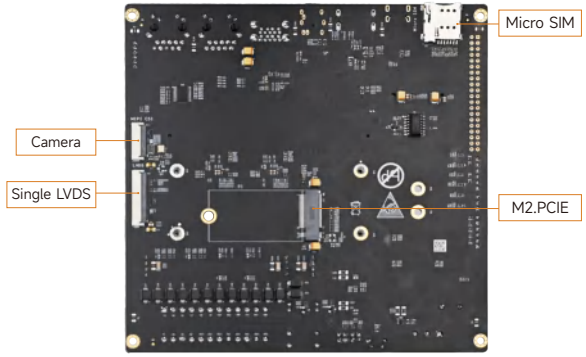
Intelligent Medical Equipment

Industrial Robot

Smart Cockpit

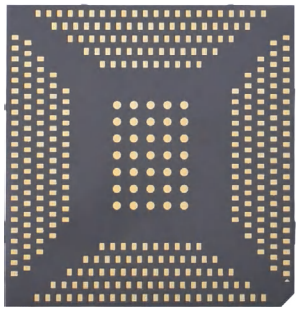


MYD-JD9360 Development Board Top-view



MYD-JD9360 Development Board Bottom-view

Rockchip | MYC-LR3568



- Rockchip RK3568 processor, 4x Cortex-A55@up to 2.0GHz + 1 Tops NPU
- LPDDR4, eMMC, EEPROM
- Supports 4K 60fps H.265/H.264/VP9 Decoder and 1080P 60fps H.265/H.264 Encoder
- Arm Mali-G52 2EE GPU with support for OpenGL ES 1.1/2.0/3.2, OpenCL 2.0, Vulkan 1.1
- 43mm x 45mm; LGA Package, 381-pin; -40°C~+85°C Industrial or -20°C~+70°C Extended; Linux / Debian

Part Selections (Other Configurations can be Customized for Mass Production)

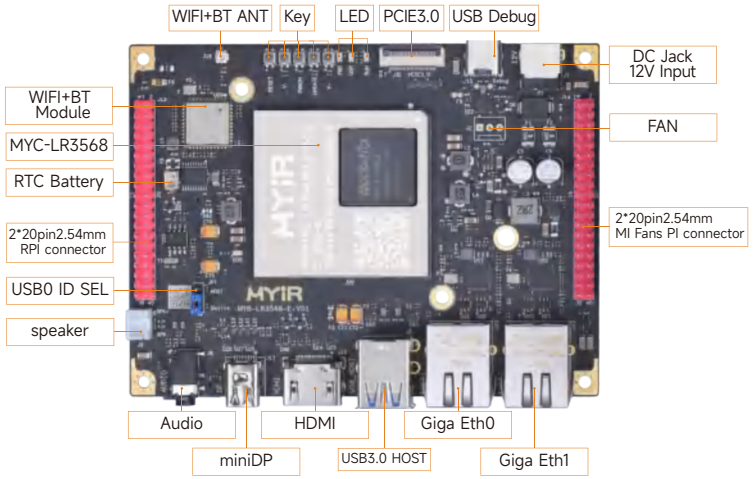
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LR3568J-16E2D-180-I	RK3568J	4×Cortex-A55@1.4GHz	2GB DDR4	16GB eMMC	32KB EEPROM	LGA 381PIN	-40°C~+85°C	43mm × 45mm	Linux Debain	MYD-LR3568J-16E2D-180-I-GK
MYC-LR3568B2-16E2D-200-E	RK3568B2	4×Cortex-A55@2.0GHz					-20°C~+70°C			MYD-LR3568B2-16E2D-200-E

Peripherals/Interfaces

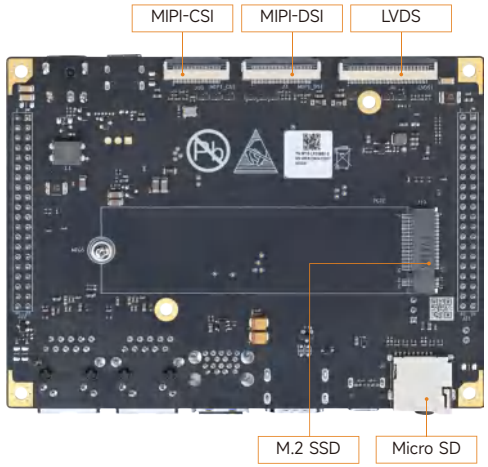
Communications	2×RGMII, 2×USB2.0, 2×USB3.0, 2×PCIe3.0, PCIe2.1, SDIO SATA3.0, 10×UART, 3×CAN, 4×SPI, 6×I2C, 16×PWM, 8×ADC
Multimedia	HDMI2.0a, eDP1.3, Dual MIPI-DSI_TX, Single LVDS, Parallel DSI 2×MIPI CSI, Parallel CSI, 4×I2S/TDM, 8×ADC

Key Applications

Industrial HMI | Charging Pile | Industrial Manufacturing | Energy & Power



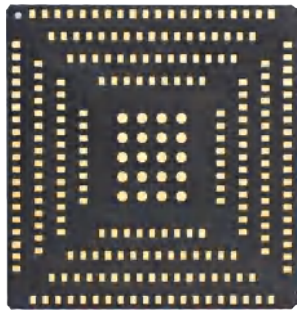
MYD-LR3568 Development Board Top-view



MYD-LR3568 Development Board Bottom-view

nuvoTon | MYC-LMA35

- Nuvoton NuMicro MA35D1 with Stacked 256MB DDR3L, 2x Cortex-A35@800MHz + Cortex-M4@180MHz
- Nand Flash / eMMC, EEPROM
- 4x CAN FD, 17x UART, 2x I2S, 6x I2C, 8x EADC, 1x JTAG, 1x RGB, 2x Parallel CSI, 18x EPWM, 4x SPI
- 2D Graphic Engine (GFX), LCD display controller with the resolution up to 1080p@60 FPS
- 37mm x 39mm; LGA Package, 252-pin; -40°C~+85°C Industrial; Linux



Part Selections (Other Configurations can be Customized for Mass Production)

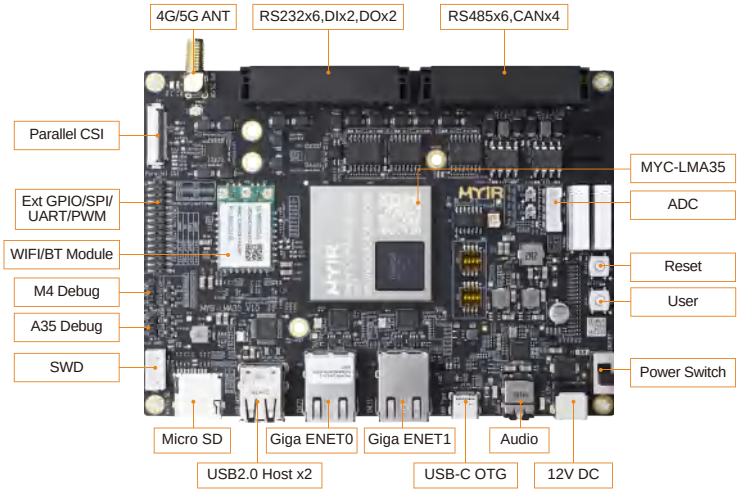
SOM Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Others	Package	Working Temp.	Dimensions	Software	Development Board Part Number
MYC-LMA35-256N256D-80-I	MA35D1	2x Cortex-A35@800MHz +Cortex-M4@180MHz	256MB DDR3L	256MB Nand Flash	32KBit EEPROM	LGA 252PIN	-40°C~+85°C	37mm × 39mm	Linux	MYD-LMA35-256N256D-80-I
MYC-LMA35-8E256D-80-I				8GB eMMC						MYD-LMA35-8E256D-80-I

Peripherals/Interfaces

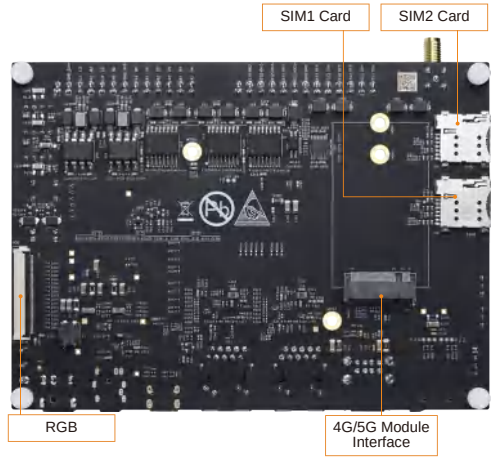
Communications	2xRGMII, 2xUSB 2.0, 17xURAT, 4xCAN FD, 6xI2C, 4xSPI
Multimedia	RGB, 2x Parallel CSI, 2xI2S
Others	JTAG, 8xEADC

Key Applications

Industrial Gateway | HMI | Motion Controller | Tiny Artificial Intelligence (AI)



MYD-LMA35 Development Board Top-view



MYD-LMA35 Development Board Bottom-view

Solutions and Applications

Single Board Computers

The embedded industrial single board computer is a complete computing system that integrates a processor, memory, storage, and various peripheral interfaces. It has gone through rigorous design and testing, exhibiting high stability and reliability, and can operate stably for long periods in harsh industrial environments. Engineers and developers can directly carry out application development and deployment on it, and it is widely used in fields such as industrial control, industrial automation, industrial data collection, medical equipment, and more.

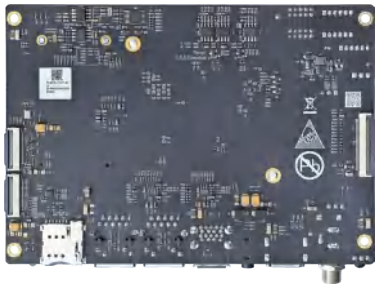
Single Board Computers

CPU Vendor / ARM Cores	RENESAS	NXP	AMD / XILINX	Texas Instruments	ALLWINNER
A7 Single-core		MYS-6ULX NXP i.MX6UL/i.MX6ULL A7@528MHz P51			
A9 Single or Dual-core			Z-turn Board V2 AMD-Xilinx XC7Z010/20 ARM: 2×A9@667MHz/766MHz, FPGA: 28K/ 85K P54 Z-turn Lite AMD-Xilinx XC7Z010 ARM: 2×A9@667MHz, FPGA: 28K P55	Rico Board TI AM437X A9@1.0GHz P53	
A53 Quad-core		MYS-8MMX-V2 NXP i.MX 8M Mini 4×A53@1.8GHz+M4@400MHz P52	FZ3 Card Xilinx XCZU3EG ARM:4xA53@1200MHz+ 2xR5@600MHz FPGA: 154K P56 FZ5 Card Xilinx XCZU5EV ARM:4xA53@1200MHz+ 2xR5@600MHz FPGA: 256K P57		
A55 Dual or Octa-core	Remi Pi Renesas RZ/G2L 2×A55@1.2GHz+M33@200MHz P50				MYD-LT527-SX Allwinner T527 8×A55@1.8GHz P49

MYD-LT527-SX

- Allwinner T527 Processor, Up to 1.8GHz Octa-core ARM Cortex-A55 MPU with GPU
- LPDDR4, eMMC, EEPROM
- 2x RS232, RS485, USB 3.0, 5x USB 2.0, 2x CAN, TF Card Slot
- 2x Gigabit Ethernet, WiFi/Bluetooth, PCIe Slot for 4G/5G Module
- 2x MIPI-CSI, HDMI/Mini-DP/MIPI-DSI/LVDS, Audio Input/Output
- Supports for Android OS

MYD-LT527-SX Top-view



MYD-LT527-SX Bottom-view

Key Applications

Medical Device

Energy & Power

Vehicle Terminals

Edge Intelligent Boxes

Features	Description
CPU	Allwinner T527 Processor, Up to 1.8GHz 8x Cortex-A55 MPU with GPU
RAM	2GB LPDDR4
ROM	16GB eMMC
Communications	1x Debug UART (TTL)
	1x RS485
	2x RS232
	2x TTL
	2x 10/100/1000M Ethernet
	1x USB2.0 Host (Type-A)
	1x USB3.0 Host (Type-A)
	4x USB2.0 Host (4-pin header connectors)
	1x Mini PCIe Interface for USB based 4G/5G Module
	1x SIM Card Slot
	1x Micro SD card slot
	2x CAN
	1x WiFi/BT Module
	1x IR RX Jack
Multimedia	1x HDMI Display Interface
	1x Dual-LVDS Display Interface
	1x eDP Display Interface
	1x MIPI-DSI Display Interface
	2x MIPI-CSI Camera Interface
	1x 3.5mm Headphone Jack
	1x MIC Interface
	1x Stereo Speaker Interface

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYD-LT527M-16E2D-180-E-SX	T527M	4xCortex-A55@1.8GHz + 4×Cortex-A55@1.4GHz RISC-V@200MHz	2GB LPDDR4	16GB eMMC	-20°C~+70°C	140mm x 100mm	Android

RENESAS | Remi Pi

- RENESAS RZ/G2L Processor, 2x Cortex-A55@1.2GHz + Cortex-M33@200MHz
- 1GB DDR4, 8GB eMMC Flash, 32KB EEPROM
- 2x USB 2.0 HOST, 1x USB 2.0 OTG, 2x Gigabit Ethernet, WiFi/Bluetooth
- Camera Interface (MIPI-CSI), LVDS, HDMI, Audio Input/Output
- Optional 7-inch LCD Modules, Camera Module and RPI Module (RS232/RS485/CAN)
- Linux OS (Yocto based with QT / Debian / Ubuntu)

Remi Pi Top-view

Remi Pi Bottom-view

Features	Description
CPU	RENESAS RZ/G2L Processor, 2x Cortex-A55@1.2GHz + Cortex-M33@200MHz
RAM	1GB DDR4
ROM	8GB eMMC
Power Management	PMIC, RAA215300
Power Supply	USB Power Supply (Type-C)
WiFi/Bluetooth	2.4GHz/5GHz WIFI + BT4.2 Module
Ethernet	2x Gigabit Ethernet Interfaces
USB	1x USB 2.0 OTG (Type-C)
	2x USB 2.0 Host (Type-A)
Multimedia	1x HDMI Display Interface
	1x LVDS Display Interface
	1x MIPI-CSI Camera Interface
	1x Audio Input/Output Interface
Debug	2x Debug UART (Cortex-A55, Cortex-M33)
Buttons	ON/OFF, RESET, USER
Status LED	Power, System Status
RPI Interface	1x 2.54mm 2x 20-pin male expansion header (GPIO/I2C/UART/SPI/CAN)
RTC	Used for timing when power off

Key Applications

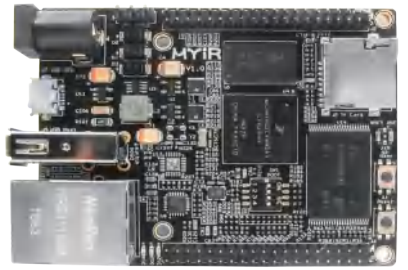
Industrial HMI | Industrial Gateway | Industrial Control | Commercial Display

Part Selections (Other Configurations can be Customized for Mass Production)

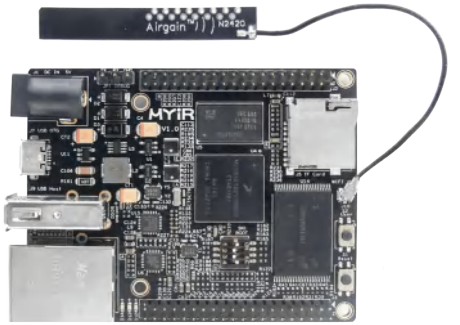
Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYD-YG2L23-8E1D-120-C-REMI	R9A07G044L23GBG	2×Cortex-A55@1.2GHz+ Cortex-M33@200MHz	1GB DDR4	8GB eMMC	0°C~+70°C	120mm x 70mm	Linux Ubuntu Debian

NXP | MYS-6ULX

- NXP i.MX 6UL/i.MX 6ULL Processor, Cortex-A7@528MHz
- 256MB DDR3, 256MB Nand Flash
- 1x USB 2.0 HOST, 1x USB 2.0 OTG, 1x 10/100Mbps Ethernet
- Optional Expansion Board adds Ethernet, CAN, RS485, Audio, RTC and Camera
- Optional 4.3 or 7 inch LCD Module, Camera and WiFi Modules
- Linux OS (Yocto based with QT / Debian)



MYS-6ULX-IND



MYS-6ULX-IOT

Features	MYS-6ULX-IND	MYS-6ULX-IOT
Target Applications	Industry 4.0	IoT Applications
CPU	MCIMX6G2CVM05AA	MCIMX6Y2DVM05AA
RAM	256MB DDR3	
ROM	256MB Nand Flash	
USB	1x USB 2.0 OTG, 1x USB 2.0 Host	
Ethernet	1x 10/100M Ethernet Interface	
TF Card	1x Micro SD Card Slot	
Key	2x Keys	
Status LED	2x User LED	
Expansion Header	2x 2.0mm pitch 2x 20-pin Male Headers (1 x Ethernet, 8 x UARTs, 4 x I2C, 2 x CAN, 4 x SPI, 8 x ADC, 4 x PWM, 2 x I2S, 1 x 8-bit Camera, 1 x JTAG, up to 46 x GPIOs)	
LCD	24-bit RGB LCD & Touch Screen (50-pin FPC connector)	
WIFI	-	1x 2.4GHz, IEEE 802.11b/g/n Standards
Working Temp.	-40°C~85°C	0°C~70°C
OS	Linux (Yocto, Debian)	Linux (Yocto, Debian)

Key Applications

Industrial HMI | Medical Device | Industrial Control | Energy & Power

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYS-6ULX-IND	MCIMX6G2CVM05AB	Cortex-A7@528MHz	256MB DDR3	256MB Nand FLASH	-40°C~+85°C	70mm x 55mm	Linux
MYS-6ULX-IOT	MCIMX6Y2CVM05AB				0°C~+70°C		

NXP | MYS-8MMX-V2

- NXP i.MX 8M Mini Processor, 4x Cortex-A53@1.8GHz + Cortex-M4@400MHz
- 2GB DDR4, 8GB eMMC Flash, 32MB QSPI FLASH
- 2x USB2.0 HOST, 1x USB2.0 OTG, Gigabit Ethernet, WiFi/Bluetooth, M.2 PCIe Interface
- Camera Interface (MIPI-CSI), LVDS, HDMI
- Supports for Yocto Linux and Ubuntu Linux OS

MYS-8MMX-V2 Box

MYS-8MMX-V2 Top-view

Features	Description
CPU	NXP i.MX 8M Mini, 4x Cortex-A53@1.8GHz + Cortex-M4@400MHz
RAM	2GB DDR4
ROM	8GB eMMC
Power Input	2 PIN Phoenix Connector
USB	1x USB 2.0 OTG (Type-C)
	2x USB 2.0 Host (Type-A)
Multimedia	1x HDMI Display Interface
	1x LVDS Display Interface
	1x MIPI-CSI Camera Interface
Ethernet	1x Gigabit Ethernet Interface
WiFi/Bluetooth	1x WIFI/BT Antenna SMA
RTC	1x 2PIN 1.25mm Pitch Connector
M.2	1x NVMe PCIe M.2 2242 SSD Slot
Expansion Interface	1x 2x25PIN 2.0mm Pitch Expansion Interface
Micro SD	1x Micro SD Card Slot
Debug	1x Debug UART, 3PIN 2.54mm Pitch
Buttons	ON/OFF, RESET, USER
Status LED	User, System Status

Key Applications

Medical Device | Energy & Power | Industrial Control | Intelligent Fire Systems

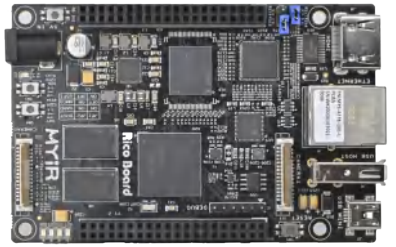
Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software	Enclosure
MYS-8MMQ6-V2-8E2D-180-C	MIMX8MM6DVTLZAA	4×Cortex-A53@1.8GHz+ Cortex-M4@400MHz	2GB DDR4	8GB eMMC	0°C~+70°C	95mm x 69mm	Linux Ubuntu	Without
MYS-8MMQ6-V2-8E2D-180-C-B						135mm x 74.5mm x 35.8mm		With
MYS-8MMQ6-V2-8E2D-160-I	MIMX8MM6CVTKZAA	4×Cortex-A53@1.6GHz+ Cortex-M4@400MHz			-40°C~+85°C	95mm x 69mm		Without
MYS-8MMQ6-V2-8E2D-160-I-B						135mm x 74.5mm x 35.8mm		With

Texas Instruments | Rico Board

- Up to 1GHz TI AM437x Sitara ARM Cortex-A9 Processor
- 512MB DDR3 SDRAM, 4GB eMMC Flash, 16MB QSPI Flash, 32KB EEPROM
- UARTs, USB Host/Device, Gigabit Ethernet, Dual-Camera, TF, …
- Supports HDMI and LCD Display
- Supports for Linux OS

Features	Description
CPU	Up to 1GHz TI AM437x Sitara ARM Cortex-A9 Processor
RAM	512MB DDR3
ROM	4GB eMMC, 16MB QSPI Flash, 32KB EEPROM
Display	24-bit true color display interface
USB	1x USB 2.0 Host port, 1x Mini USB 2.0 Device port
HDMI	1x HDMI Display interface
TF Card	1x TF card interface
Camera	2x Camera interfaces
Ethernet	1x Gigabit Ethernet Interface
UART	1x Debug UART
JTAG	1x 20-pin JTAG interface
Expansion Interface	2x SPI, 2x I2C, 2x CAN, 4x UARTs, 1x MMC, 8x ADC
PCB	8-layer design
Dimensions	65mm x 100mm
OS Support	Linux



Rico Board Top-view

Rico Board Bottom-view

Key Applications

Industrial HMI | Medical Device | Industrial Control | Scanner

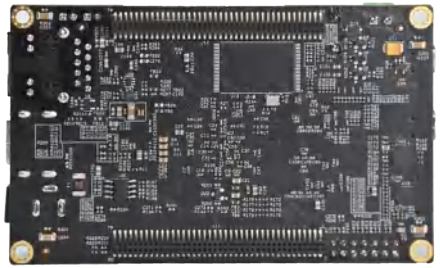
Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software	Accessories
MYS-4378-100-C	AM4378BZDN100	Cortex-A9@1.0GHz	512MB DDR3	4GB eMMC	0°C~+70°C	100mm x 65mm	Linux	With
MYS-4378-100-C-S								Without

Z-turn Board V2

- Xilinx XC7Z010/20 Processor, 2*Cortex-A9@667MHz+Artix 7 FPGA
- 1GB DDR3, 16MB QSPI Flash, 64Kbit EEPROM
- USB_UART, USB2.0 OTG, 1 x 10/100/1000Mbps Ethernet, CAN, HDMI, TF, ...
- Onboard Three-axis Acceleration Sensor and Temperature Sensor
- Supports Optional Camera Module and Z-turn IO Cape
- Ready-to-Run Linux Single Board Computer
- Supports Python Development

Z-turn Board V2 Top-view



Z-turn Board V2 Bottom-view

Features	Description
CPU	Xilinx XC7Z010/XCZ7020
RAM	1GB DDR3 SDRAM
ROM	16MB QSPI Flash
Sensor	Onboard Three-axis Acceleration Sensor, Temperature Sensor
USB	1 x Mini USB2.0 OTG, 1 x USB-UART debug interface
HDMI	1 x HDMI (supports 1080p resolution)
TF	1 x TF card interface
CAN	1 x CAN
Ethernet	1x 10/100/1000Mbps Ethernet Interface
User I/O	2x 1.27mm pitch 80-pin SMT female connectors
	PLIO: 90/106 (XC7Z010/XC7Z020)
Dimensions	63mm x 102mm x 1.6mm (8-layer PCB design)
OS support	Linux

Key Applications

Automotive | Medical Device | Industrial | Visual Monitoring

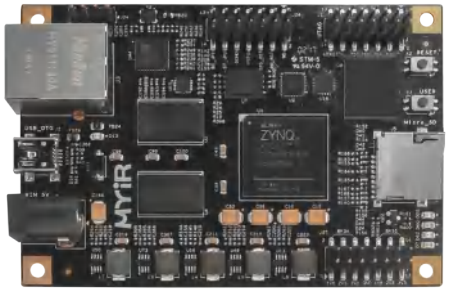
Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software	Accessories
MYS-7Z010-V2-0E1D-667-C	XC7Z010-1CLG400	2×Cortex-A9@667Hz +Atrix 7 FPGA (28K)	1GB DDR3	16MB QSPI Flash	0°C~+70°C	63mm × 102mm	Linux	With
MYS-7Z010-V2-0E1D-667-C-S								Without
MYS-7Z020-V2-0E1D-766-C	XC7Z020-2CLG400	2×Cortex-A9@766Hz +Atrix 7 FPGA (85K)						With
MYS-7Z020-V2-0E1D-766-C-S								Without

AMD XILINX | Z-turn Lite

- Xilinx XC7Z010 Processor, 2*Cortex-A9@667MHz+Artix 7 FPGA
- 512MB DDR3, 4GB eMMC, 16MB QSPI Flash
- USB2.0 OTG, 10/100/1000M Ethernet, TF, Debug UART, JTAG…
- One 120 Position Connector Socket for Expansion interface
- Ready-to-Run Linux Single Board Computer
- Optional Camera and LCD Modules, IO Extension Cape

Features	Description
CPU	Xilinx XC7Z010
RAM	512MB DDR3 SDRAM
ROM	4GB eMMC Flash, 16MB QSPI Flash
Ethernet	1x 10/100/1000Mbps Ethernet Interface
USB	1 x Mini USB2.0 OTG
Input and Output	1 x 2.54mm pitch 14-pin JTAG Interface
	1 x 0.5mm pitch 120 Position Connector Socket for Expansion Interface
	1 x 2.54mm pitch 4-pin Debug UART Interface
TF	1 x TF card interface
Buttons	1x Reset, 1 x User
Dimensions	91mm x 63mm (10-layer PCB design)
OS support	Linux



Z-turn Lite Top-view

Z-turn Lite Bottom-view

Key Applications

Automotive

Medical Device

Industrial

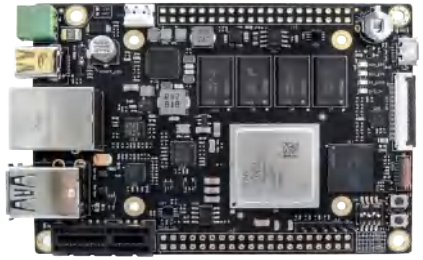
Visual Monitoring

Part Selections (Other Configurations can be Customized for Mass Production)

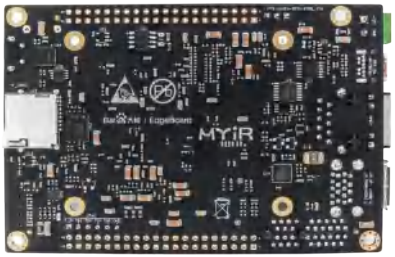
Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Other Storage	Working Temp	Dimensions	Software	Accessories
MYS-7Z010-L-C	XC7Z010-1CLG400	2×Cortex-A9@667Hz +Atrix 7 FPGA (28K)	512MB DDR3	4GB eMMC	16MB QSPI Flash	0°C~+70°C	91mm x 63mm	Linux	With
MYS-7Z010-L-C-S									Without

AMD XILINX | FZ3 Card

- Xilinx Zynq UltraScale+ ZU3EG MPSoC Processor, 4*Cortex-A53@1.2GHz+2*Cortex-R5@600MHz
- DDR4, eMMC, QSPI Flash, EEPROM
- USB2.0, USB3.0, Gigabit Ethernet, TF, DP, PCIe, MIPI-CSI, BT1120, USB-UART, JTAG…
- Computing Power up to 1.2TOPS, MobileNet up to 100FPS
- Ready-to-Run PetaLinux 2020.1
- Supports Xilinx Vitis Software Development Platform



FZ3 Card Top-view



FZ3 Card Bottom-view

Features	Description
CPU	XCZU3EG
RAM	4GB DDR4 (64-bit)
ROM	8GB eMMC
QSPI FLASH	32MB QSPI
EEPROM	32KB I2C EEPROM
PHY	1x Gigabit PHY
	2x USB 2.0 PHY
Mini DP	4K/30fps (2lane)
Ethernet	1x Gigabit Ethernet Interface
USB	1x USB 2.0 Host, 1x USB 3.0 Host
PCIe	PCIe 2.1 x 1 lane
MIPI	FPC_25PIN 4lane
BT1120	FPC_32PIN 16bit
Debug	1x Mini USB-to-UART Port
Expansion IOs	2x 2.54mm pitch 2 x 20-pin IO Expansion Interfaces
PCB	12-layer Design
Dimensions	100mm x 70mm

Key Applications

Security Monitoring | Industrial Quality Assurance | Medical Device | Artificial Intelligence (AI)

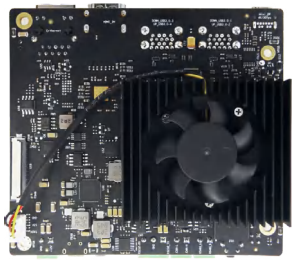
Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Other Storage	Software	Accessories
MYS-ZU3EG-8E4D-EDGE-K2	XCZU3EG-1SFVC784I	ARM: 4×A53@1200MHz+ 2×R5@533MHz+ UltraScale+ FPGA 154K	4GB DDR4	8GB eMMC	-40°C~+85°C	32MB QSPI FLASH 32Kbit EEPROM	Linux	With
MYS-ZU3EG-8E4D-EDGE								Without

FZ5 Card

- Zynq UltraScale+ XCZU5EV MPSoC, 4*Cortex-A53@1.2GHz+2*Cortex-R5@600MHz+FPGA
- Computing Power up to 2.4TOPS, Runs at 55 FPS for ResNet-50
- 8GB DDR4, 32GB eMMC, 64MB QSPI Flash, 32KB EEPROM
- RS232, RS485, 4 x USB 3.0, Gigabit Ethernet, CAN, TF, DP, HDMI-IN, JTAG…
- Supports 8- to 16-channel Video Decoding and 4- to 8-channel Intelligent Analysis
- Ready-to-Run PetaLinux 2020.1

FZ5 Card Top-view



FZ5 Card Bottom-view

FZ5 EdgeBoard AI Box Front-view

FZ5 EdgeBoard AI Box Back-view

Features	Description
CPU	XCZU5EV
RAM	8GB DDR4 (64bit, 2400MHz)
ROM	32GB eMMC
QSPI FLASH	64MB QSPI
EEPROM	32KB EEPROM
Serial Ports	1x RS232, 1x RS485, 1 x USB-UART Debug
Ethernet	1x Gigabit Ethernet
USB3.0	4x USB3.0 Host
CAN	1x CAN
HDMI	1x HDMI In
MIPI DP	1x Mini DisplayPort (DP), 4K/30fps
User I/O	1 x FPC_40PIN (Reserved for MIPI-CSI)
	1 x 1.27mm pitch 2 x 50-pin IO Expansion Interface (5 x PS_MIO, 69 x PL_IO)

Key Applications

Intelligent Security | Medical Diagnosis | Artificial Intelligence (AI) | Consumer Electronics

Part Selections (Other Configurations can be Customized for Mass Production)

Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Other Storage	Software
MYS-ZU5EV-32E8D-EDGE-K1	XCZU5EV-2SFVC784I	ARM: 4×A53@1200MHz+2×R5@600MHz FPGA: 256K	8GB DDR4	32GB eMMC	-40°C~+85°C	64MB QSPI Flash	Linux
MYS-ZU5EV-32E8D-EDGE-BOX						32KB EEPROM	

Solutions and Applications

Industrial Personal Computer (IPC) Box

The Industrial Personal Computer (IPC) Box is an embedded computer specially designed for industrial control applications, adopting an integrated design, integrating the single board computer, communication module, components and enclosure in a single device, the whole computer has the features of anti-interference, high and low temperature resistance, dustproof and waterproof, and long time and stable operation, etc. It is widely used in industrial automation, instrumentation testing, data acquisition, Internet of Things, intelligent transportation, energy management, medical equipment, rail transportation and other industries.

- MYD-LR3568-GK-B P59

Rockchip | MYD-LR3568-GK-B

- Rockchip RK3568 Application Processor based on Up to 1.8GHz Quad ARM Cortex-A55 Cores
- LPDDR4, eMMC, EEPROM
- 2x USB 3.0, 3x USB 2.0, 2x CAN, RS232, 2x RS485, Debug (USB-UART), Micro SD Card Slot
- 2x Gigabit Ethernet, WiFi/Bluetooth, PCIe Slot for 4G Module
- Supports Mini-DP and HDMI for High-resolution Displays, along with Audio Input/Output Interface
- Supports Linux and Debian OS

MYD-LR3568-GK-B Front-view

MYD-LR3568-GK-B Back-view

Features	Description
CPU	Rockchip RK3568 Processor, Up to 1.8GHz Quad ARM Cortex-A55 Cores
RAM	2GB/4GB LPDDR4
ROM	16GB/32GB eMMC
EEPROM	32KB EEPROM
Communications	1x USB-UART Debug Interface
	1x RS232
	2x RS485
	2x USB 3.0 Host Ports
	3x USB 2.0 Host Ports
	2x 10/100/1000Mbps Ethernet Interfaces
	2x CAN
	WiFi/Bluetooth Module
	1x WiFi/BT antenna interface
	1x M.2 Socket for a USB-based 4G LTE Module
	1x SIM card holder
Multimedia	1x HDMI 2.0 Interface
	1x Mini DisplayPort (DP) Output Interface
	1x 3.5mm Headphone/Mic Audio Jack

Key Applications

Industrial Personal Computer

Multi-screen HD Player

Power Measurement & Control Terminal

Data Acquisition

Part Selections (Other Configurations can be Customized for Mass Production)

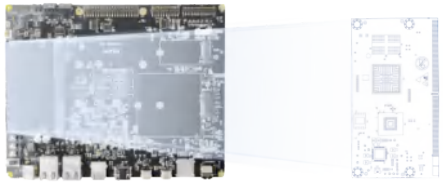
Part Number	CPU	CPU Cores and Clock Speed (Max)	RAM	ROM	Working Temp	Dimensions	Software
MYD-LR3568J-16E2D-180-I-GK-B	RK3568J	4xCortex-A55@Up to 1.8GHz	2GB LPDDR4	16GB eMMC	-40°C~+85°C	130mm x 93.5mm x 44mm (without mounting bracket) 160mm x 93.5mm x 44mm (with mounting bracket)	Linux Debian
MYD-LR3568J-32E4D-180-I-GK-B			4GB LPDDR4	32GB eMMC			

ODM Services

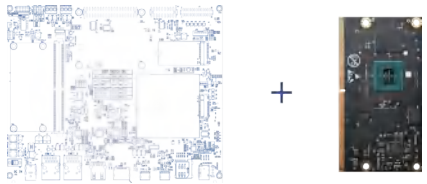
Based on years of experience in the embedded industry, MYIR has amassed extensive product technology and project development expertise in embedded software and hardware development utilizing ARM/FPGA core processors. MYIR also offers professional and efficient customized services tailored to the specific requirements of customers.

Customized Solutions

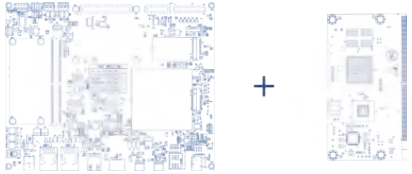
SoM Customization



Base Board Customization



Whole Board Customization



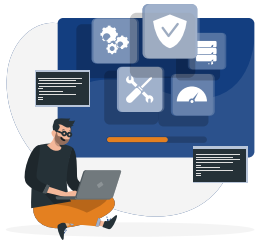
Customized Service Process

1 Submit Requirements

2 Technical Evaluation

3 Business Communication

4 Sign Contract



5 Project Development

6 Prototype Delivery

7 Testing and Certification

8 Customer Acceptance

9 Mass Delivery

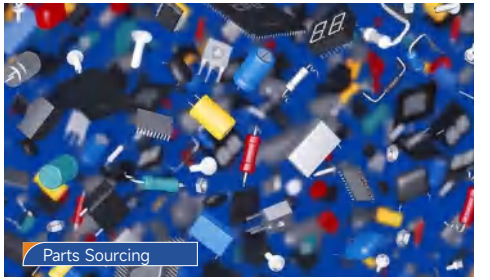
OEM Services

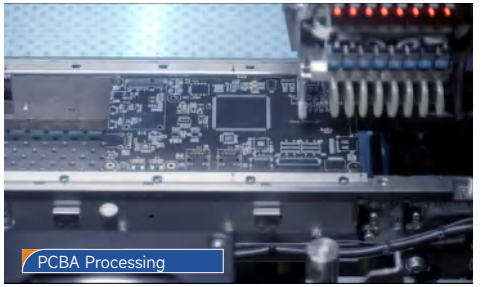
MYIR's Smart SMT factory is committed to providing customers with one-stop PCBA manufacturing services, encompassing PCB manufacturing, component procurement, SMT processing, assembly, and testing. Located in Longhua District, Shenzhen, the factory utilizes its advanced production equipment and management system, rigorous quality control procedures, comprehensive supply chain system, and robust engineering support to assist customers in enhancing production efficiency, reducing product delivery time, and ensuring production quality. It caters to a diverse range of customers across various industries, including industrial control, power communication, new energy, automotive electronics, medical electronics, smart home, security, and numerous other sectors globally.

One-stop PCBA Manufacturing Service

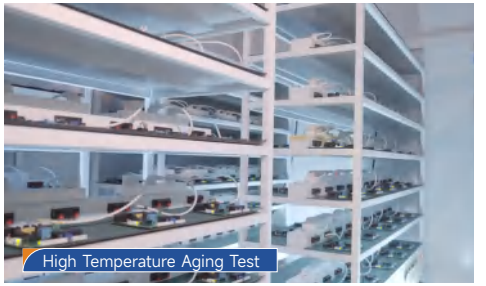

DFM (Design for Manufacturing)

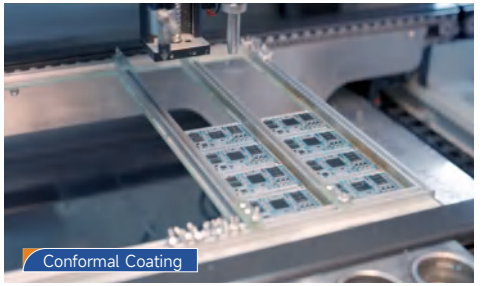

PCB Fabrication


Parts Sourcing


PCBA Processing


Program Burning and Testing


High Temperature Aging Test


Conformal Coating


Finished Product Assembly

OEM Services Cover Many Industries

Industrial Control | Power Communication | New Energy | Automotive Electronics | Medical Instruments | Intelligent Security | Engineering Machinery | Rail Transit | Industrial Gateway

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Shenzhen Factory

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Wuhan R&D Center

Room 1601, Building No. 4, Dangdai Science Park, No. 20, Guannanyuan 1st Road, Wuhan East Lake New Technology Development Zone Wuhan, China

Beijing Branch

Room 901, Building No. 10, Lipo Plaza, No. 8, Ronghua Middle Road, Daxing District, Beijing, China

Shanghai Branch

Room 805, Building No. 1, Pudong Jiangcheng Plaza, No. 778, Jinji Road, Pudong New Area, Shanghai, China